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Reiherzer et al.

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(54) **LIGHT EMITTING DIODE DEVICE**

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(52) **U.S. Cl.**
USPC **D13/180**

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See application file for complete search history.

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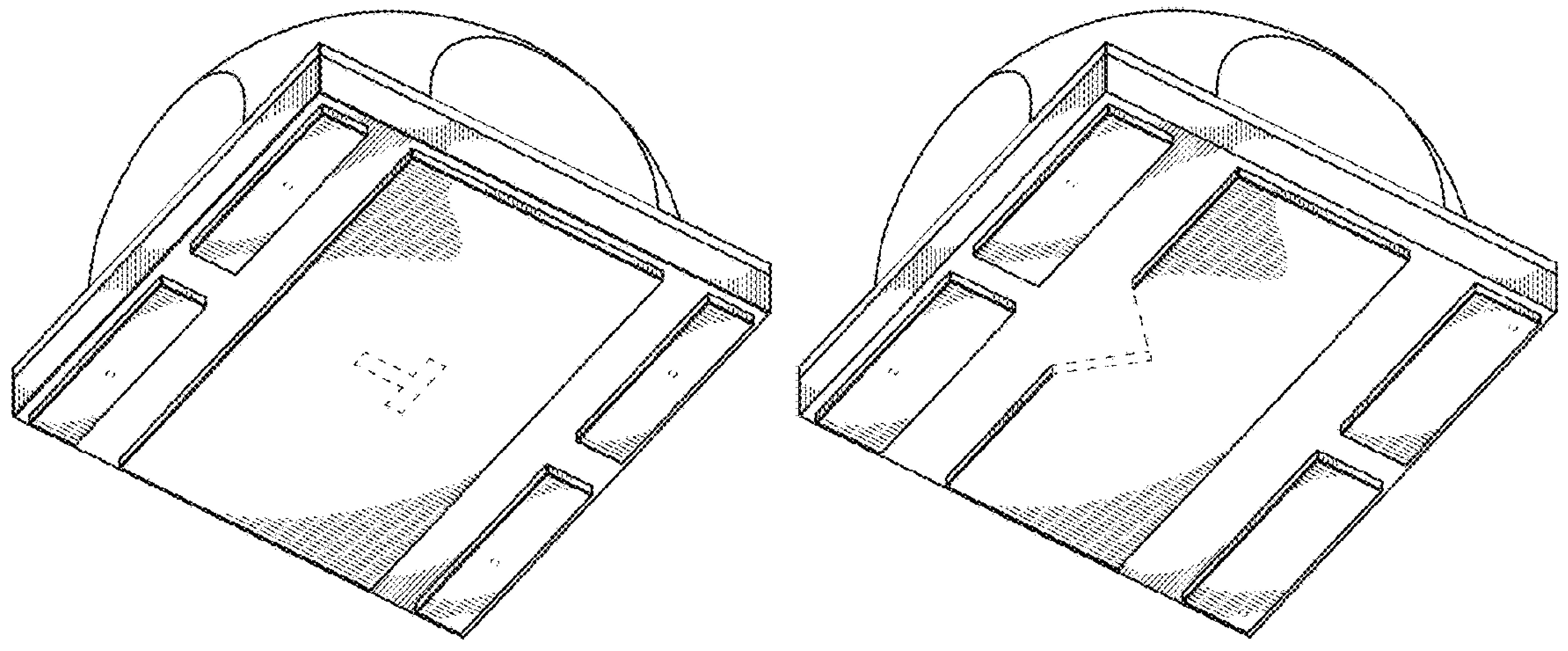

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(57) CLAIM

The ornamental design for light emitting diode device, as shown and described herein.

DESCRIPTION

FIG. **1** is a bottom perspective view of a light emitting diode device according to an embodiment of the present invention.
FIG. **2** is a top view of the light emitting diode device shown in FIG. **1**.
FIG. **3** is a bottom view of the light emitting diode device shown in FIG. **1**.
FIG. **4** is a front elevation view of the light emitting diode device shown in FIG. **1**.
FIG. **5** is a right side elevation view of the light emitting diode device shown in FIG. **1**.
FIG. **6** is a back elevation view of the light emitting diode device shown in FIG. **1**.
FIG. **7** is a left side elevation view of the light emitting diode device shown in FIG. **1**.
FIG. **8** is a bottom perspective view of a light emitting diode device according to an embodiment of the present invention.
FIG. **9** is a top view of the light emitting diode device shown in FIG. **8**.
FIG. **10** is a bottom view of the light emitting diode device shown in FIG. **8**.
FIG. **11** is a front elevation view of the light emitting diode device shown in FIG. **8**.
FIG. **12** is a right side elevation view of the light emitting diode device shown in FIG. **8**.
FIG. **13** is a back elevation view of the light emitting diode device shown in FIG. **8**.
FIG. **14** is a left side elevation view of the light emitting diode device shown in FIG. **8**.
FIG. **15** is a bottom perspective view of a light emitting diode device according an embodiment of to the present invention.
FIG. **16** is a top view of the light emitting diode device shown in FIG. **15**.
FIG. **17** is a bottom view of the light emitting diode device shown in FIG. **15**.
FIG. **18** is a front elevation view of the light emitting diode device shown in FIG. **15**.
FIG. **19** is a right side elevation view of the light emitting diode device shown in FIG. **15**.
FIG. **20** is a back elevation view of the light emitting diode device shown in FIG. **15**.
FIG. **21** is a left side elevation view of the light emitting diode device shown in FIG. **15**.

FIG. **22** is a bottom perspective view of a light emitting diode device according to an embodiment of the present invention.

FIG. **23** is a top view of the light emitting diode device shown in FIG. **22**.

FIG. **24** is a bottom view of the light emitting diode device shown in FIG. **22**.

FIG. **25** is a front elevation view of the light emitting diode device shown in FIG. **22**.

FIG. **26** is a right side elevation view of the light emitting diode device shown in FIG. **22**.

FIG. **27** is a back elevation view of the light emitting diode device shown in FIG. **22**.

FIG. **28** is a left side elevation view of the light emitting diode device shown in FIG. **22**.

FIG. **29** is a bottom perspective view of a light emitting diode device according to an embodiment of the present invention.

FIG. **30** is a top view of the light emitting diode device shown in FIG. **29**.

FIG. **31** is a bottom view of the light emitting diode device shown in FIG. **29**.

FIG. **32** is a front elevation view of the light emitting diode device shown in FIG. **29**.

FIG. **33** is a right side elevation view of the light emitting diode device shown in FIG. **29**.

FIG. **34** is a back elevation view of the light emitting diode device shown in FIG. **29**.

FIG. **35** is a left side elevation view of the light emitting diode device shown in FIG. **29**.

FIG. **36** is a bottom perspective view of a light emitting diode device according to an embodiment of the present invention.

FIG. **37** is a top view of the light emitting diode device shown in FIG. **36**.

FIG. **38** is a bottom view of the light emitting diode device shown in FIG. **36**.

FIG. **39** is a front elevation view of the light emitting diode device shown in FIG. **36**.

FIG. **40** is a right side elevation view of the light emitting diode device shown in FIG. **36**.

FIG. **41** is a back elevation view of the light emitting diode device shown in FIG. **36**; and,

FIG. **42** is a left side elevation view of the light emitting diode device shown in FIG. **36**.

The broken lines of FIGS. **1-42** illustrate portions of the various embodiments of the light emitting diode device which form no part of the claimed design.

1 Claim, 12 Drawing Sheets

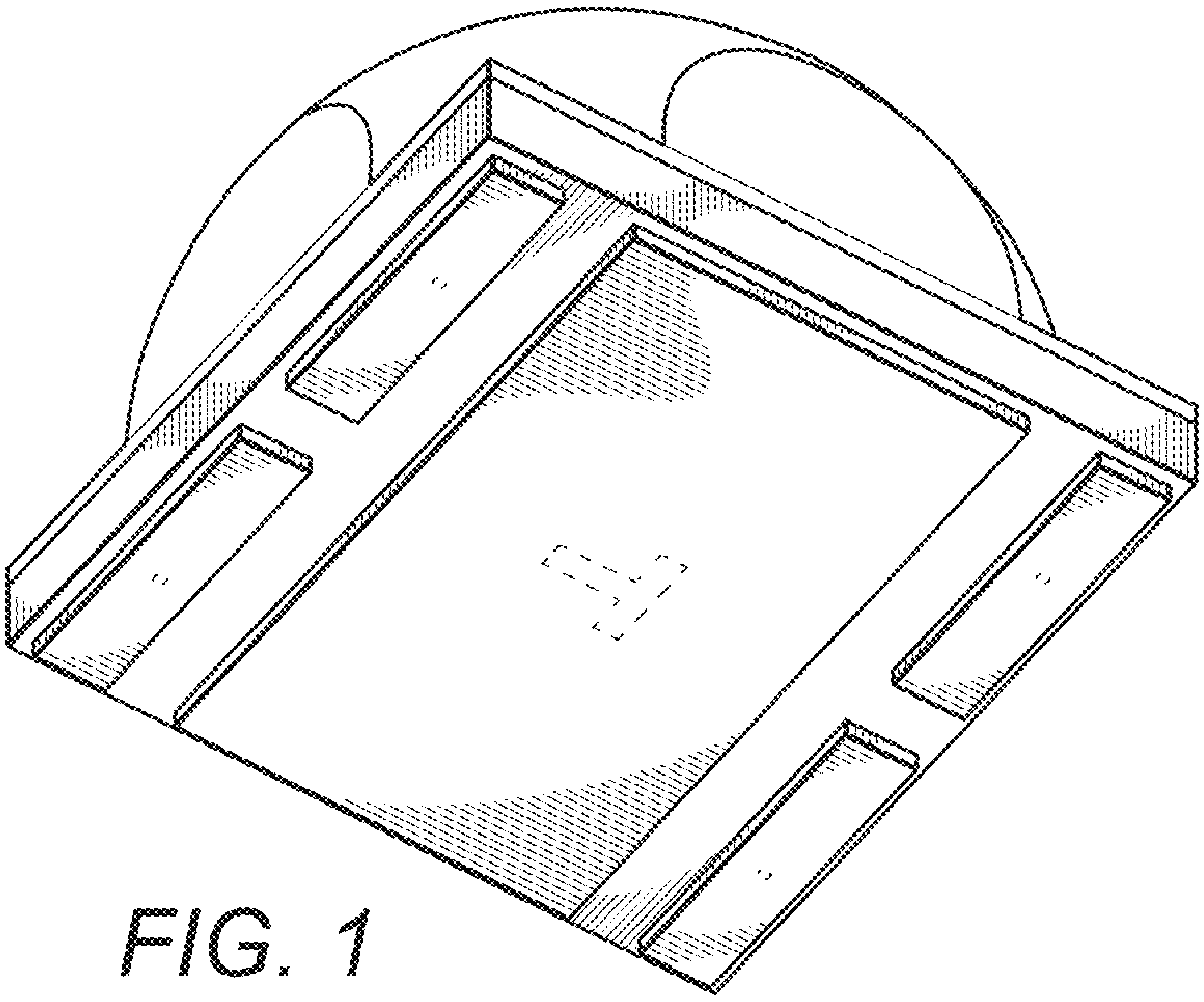


FIG. 1

FIG. 2

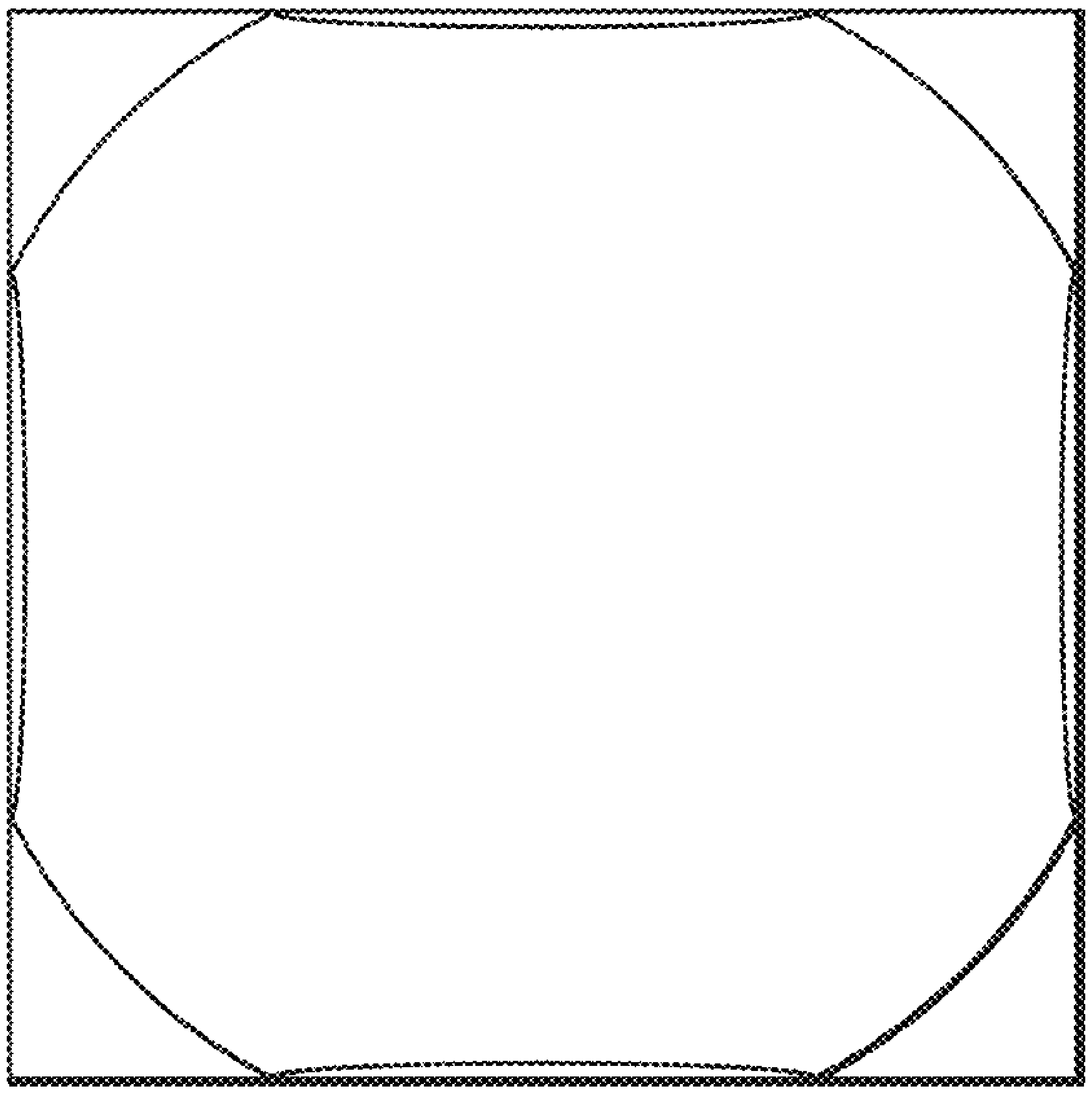
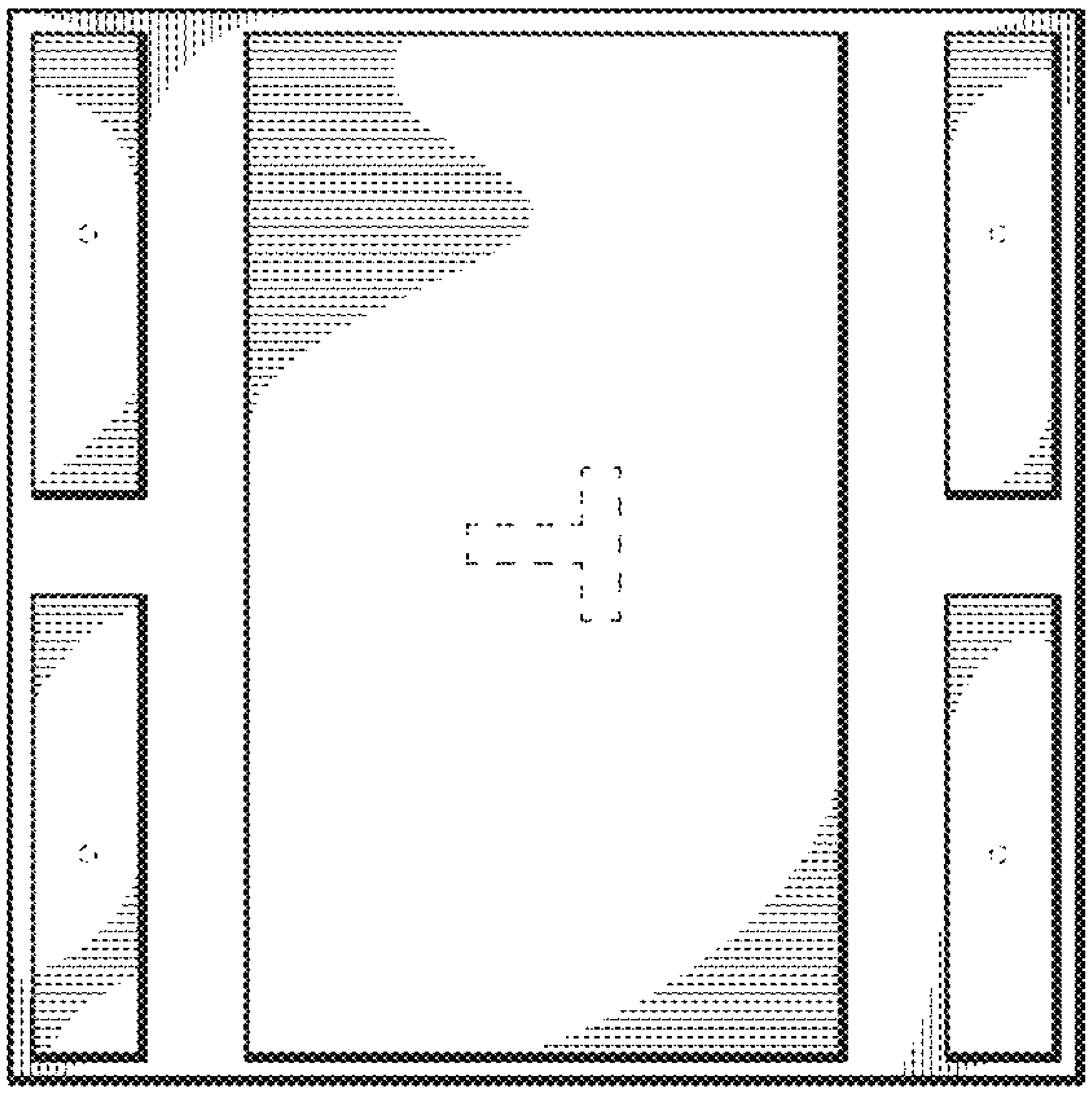


FIG. 3



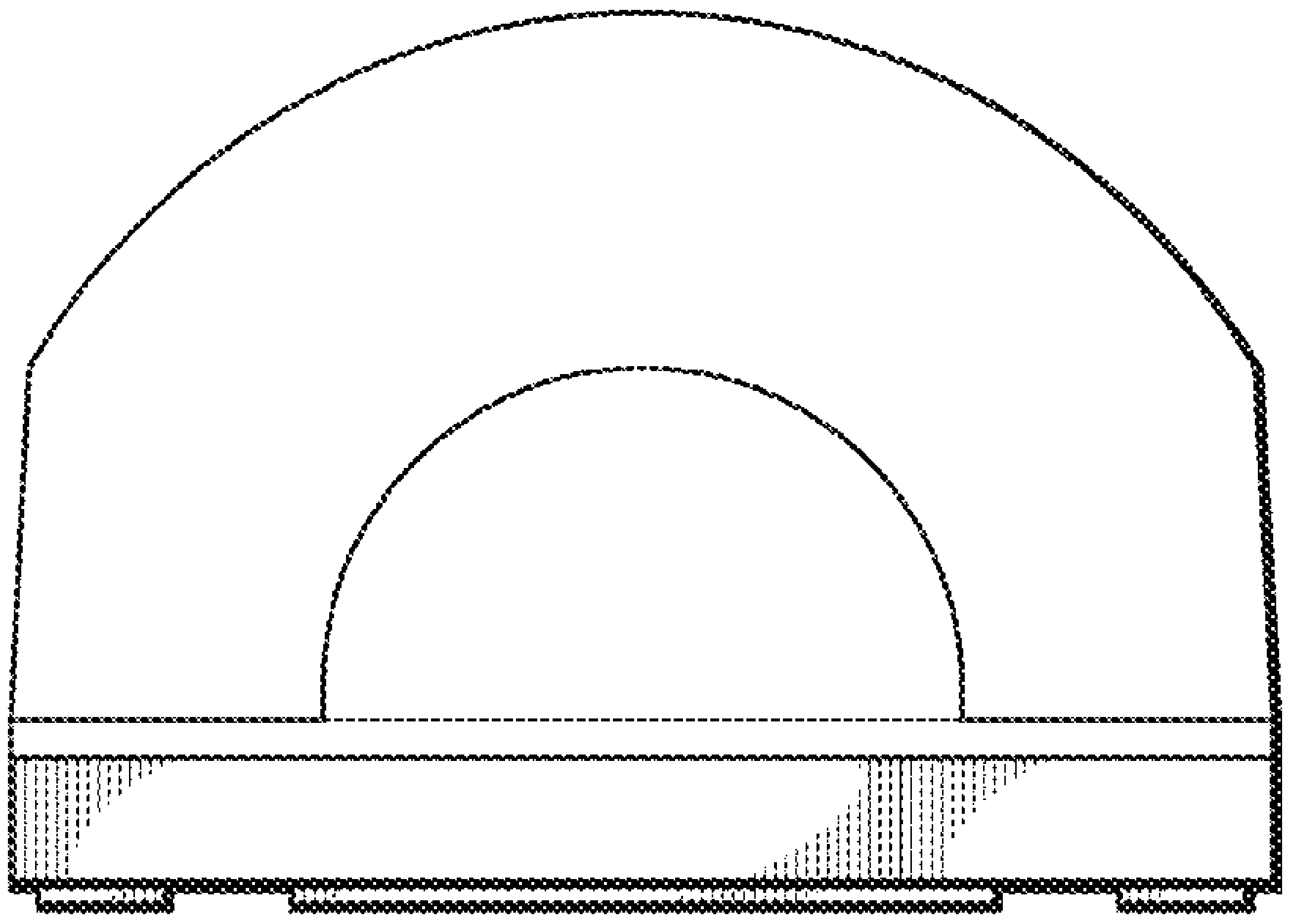


FIG. 4

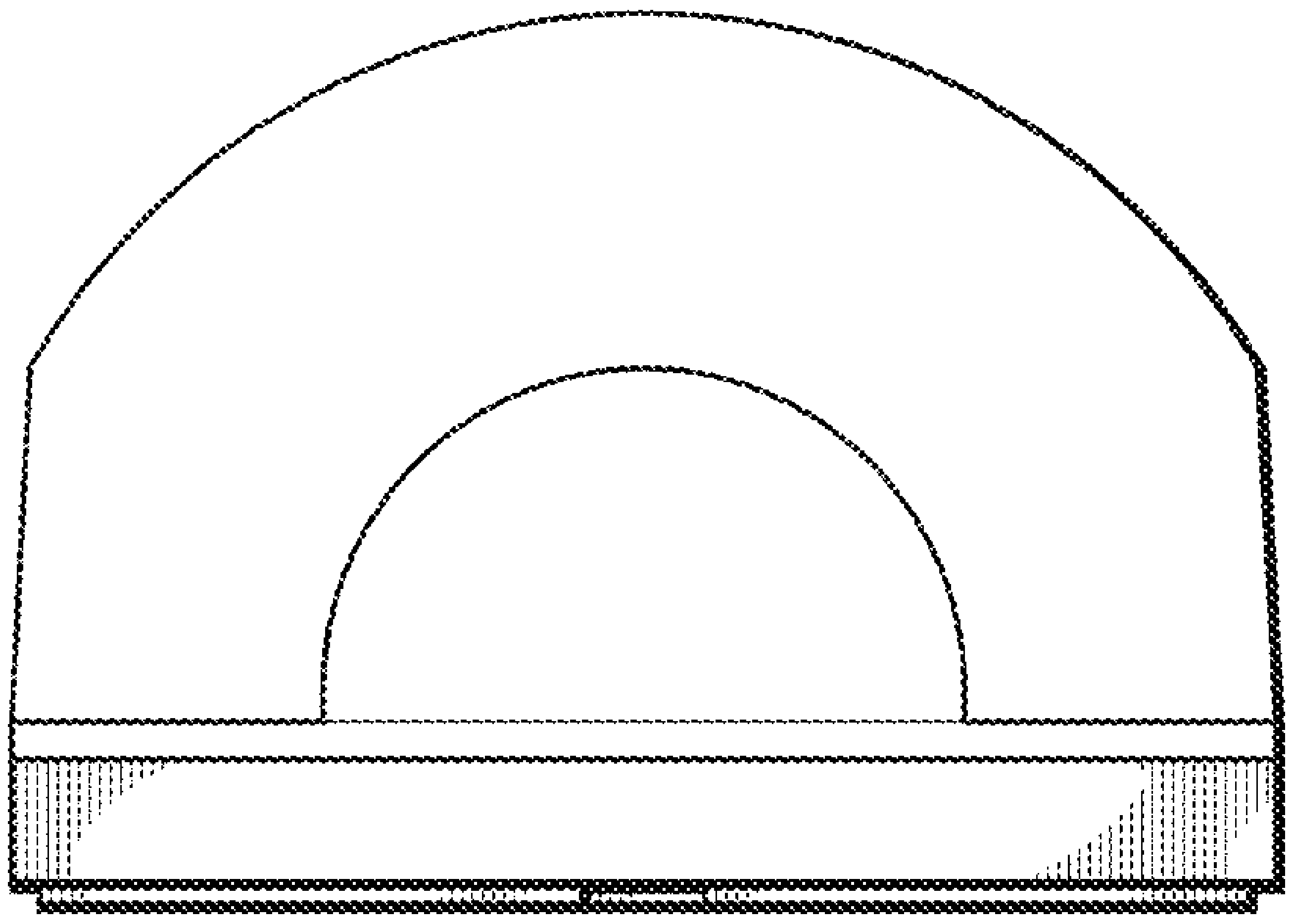


FIG. 5

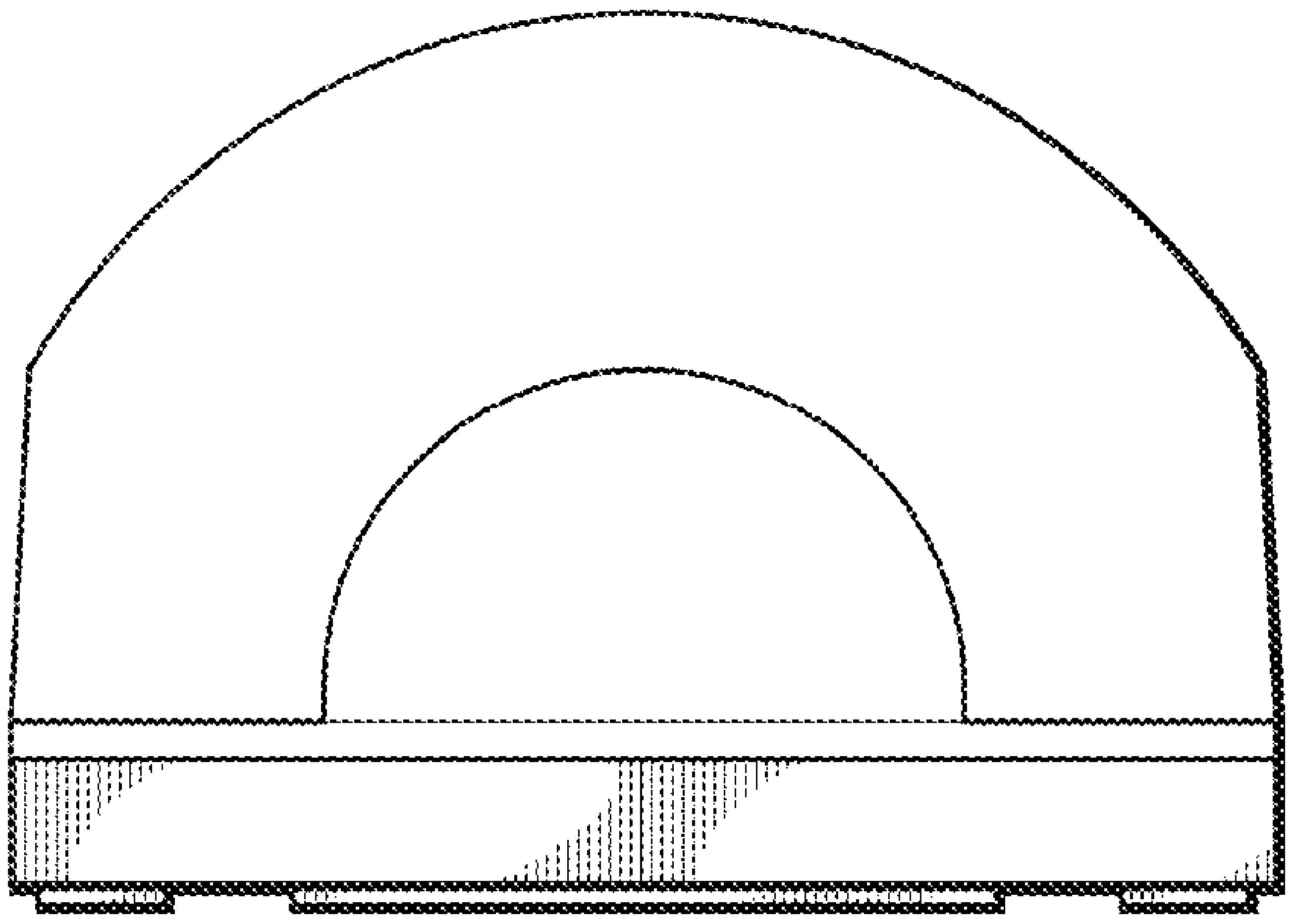


FIG. 6

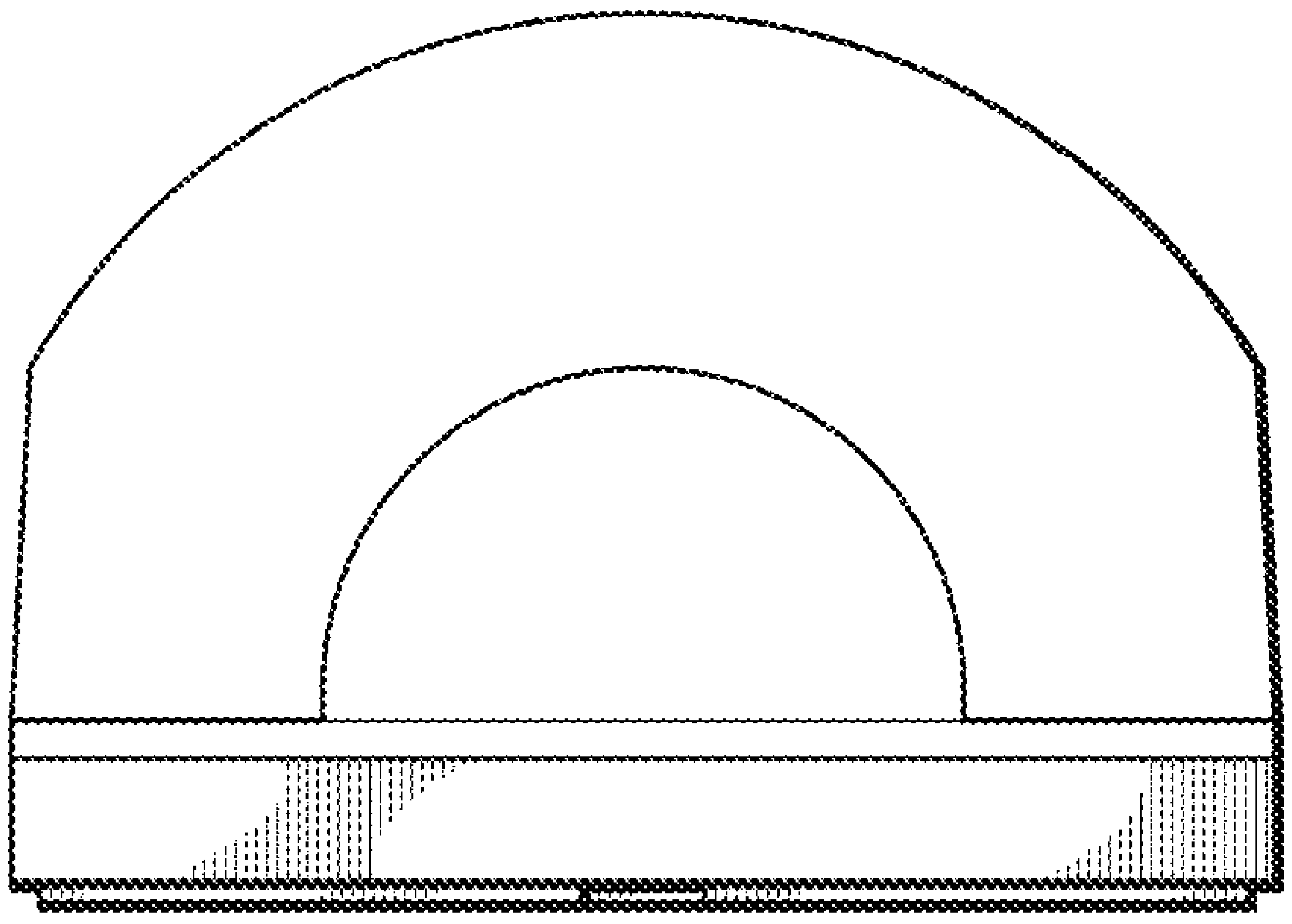


FIG. 7

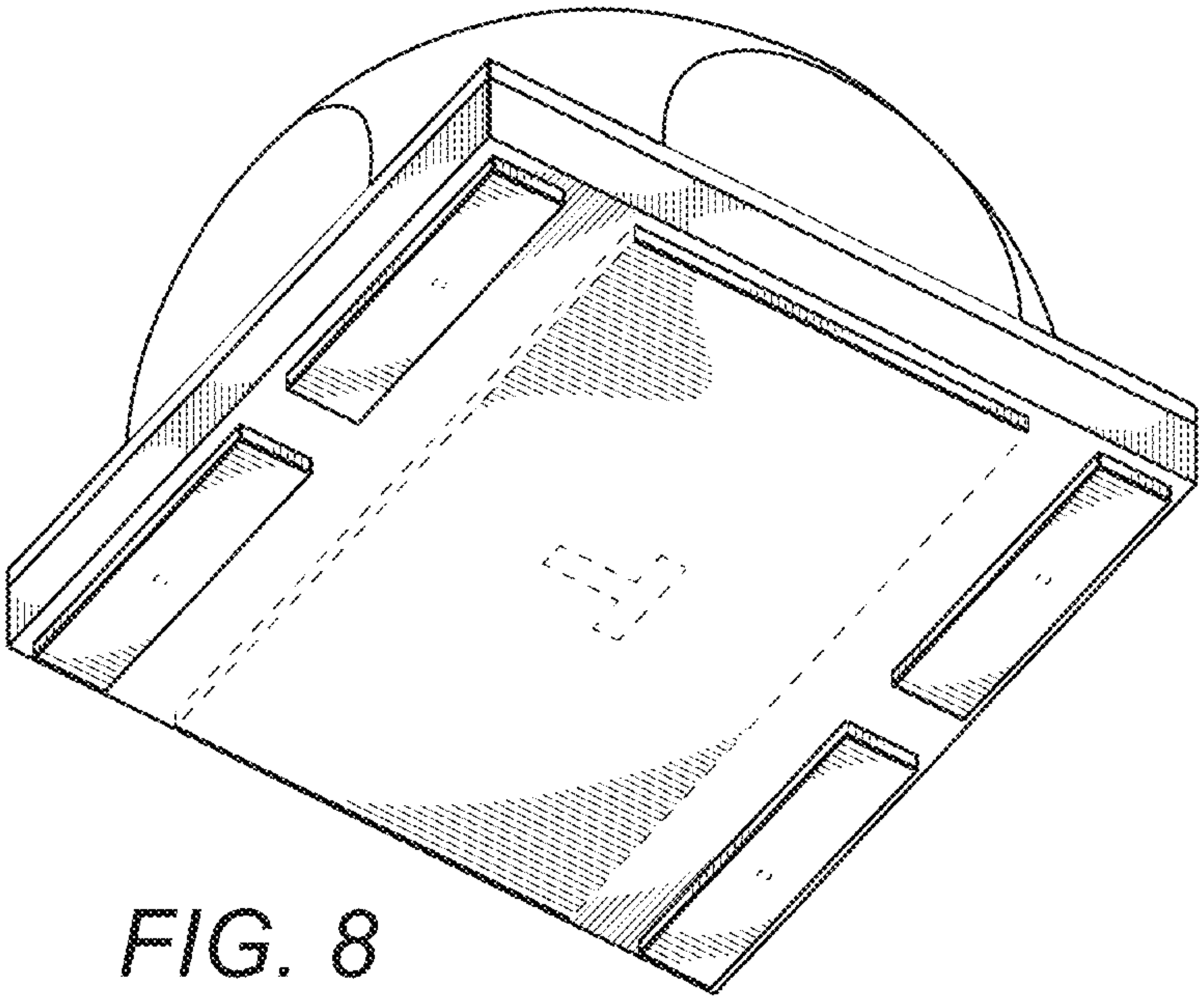


FIG. 8

FIG. 9

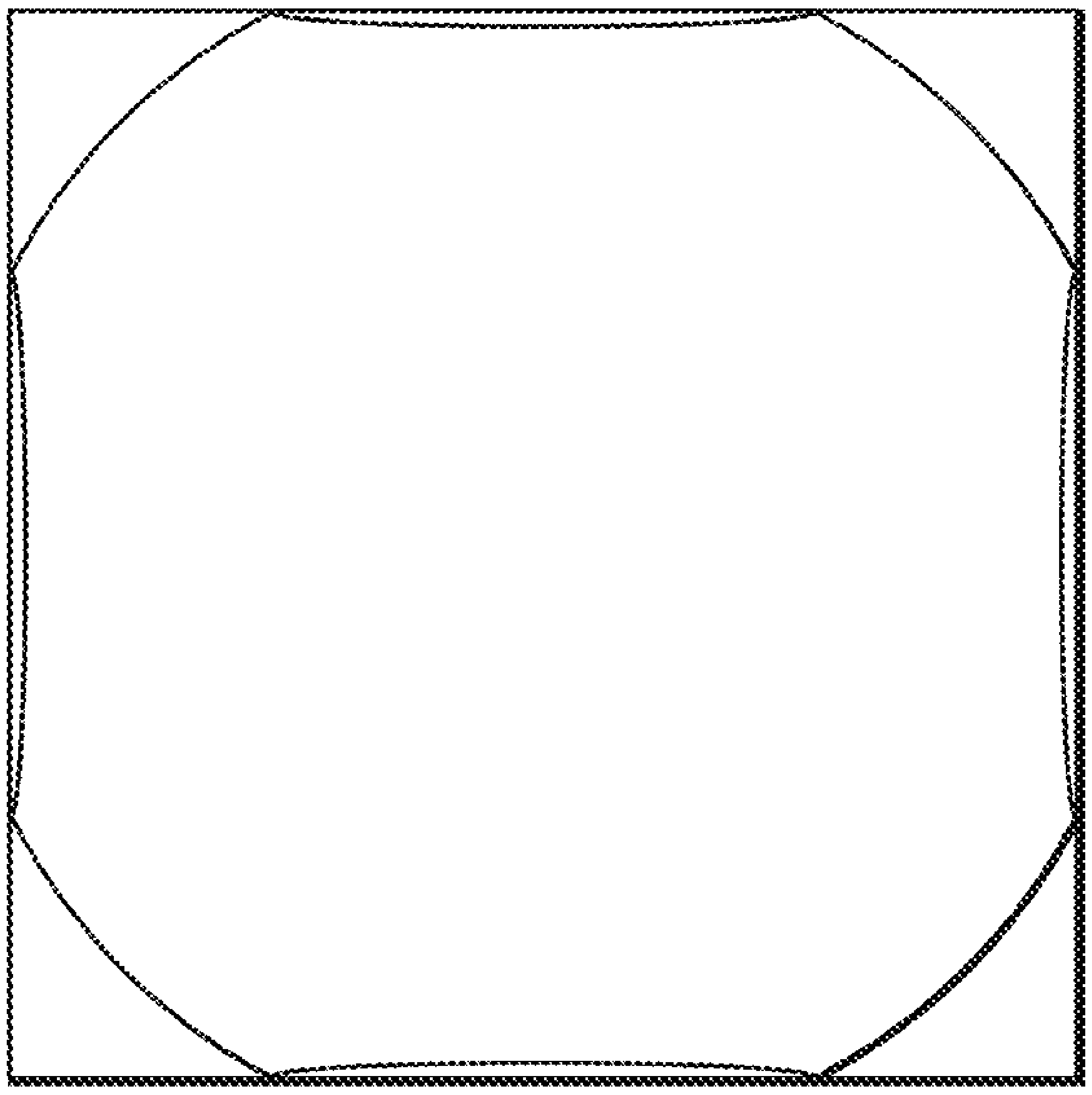
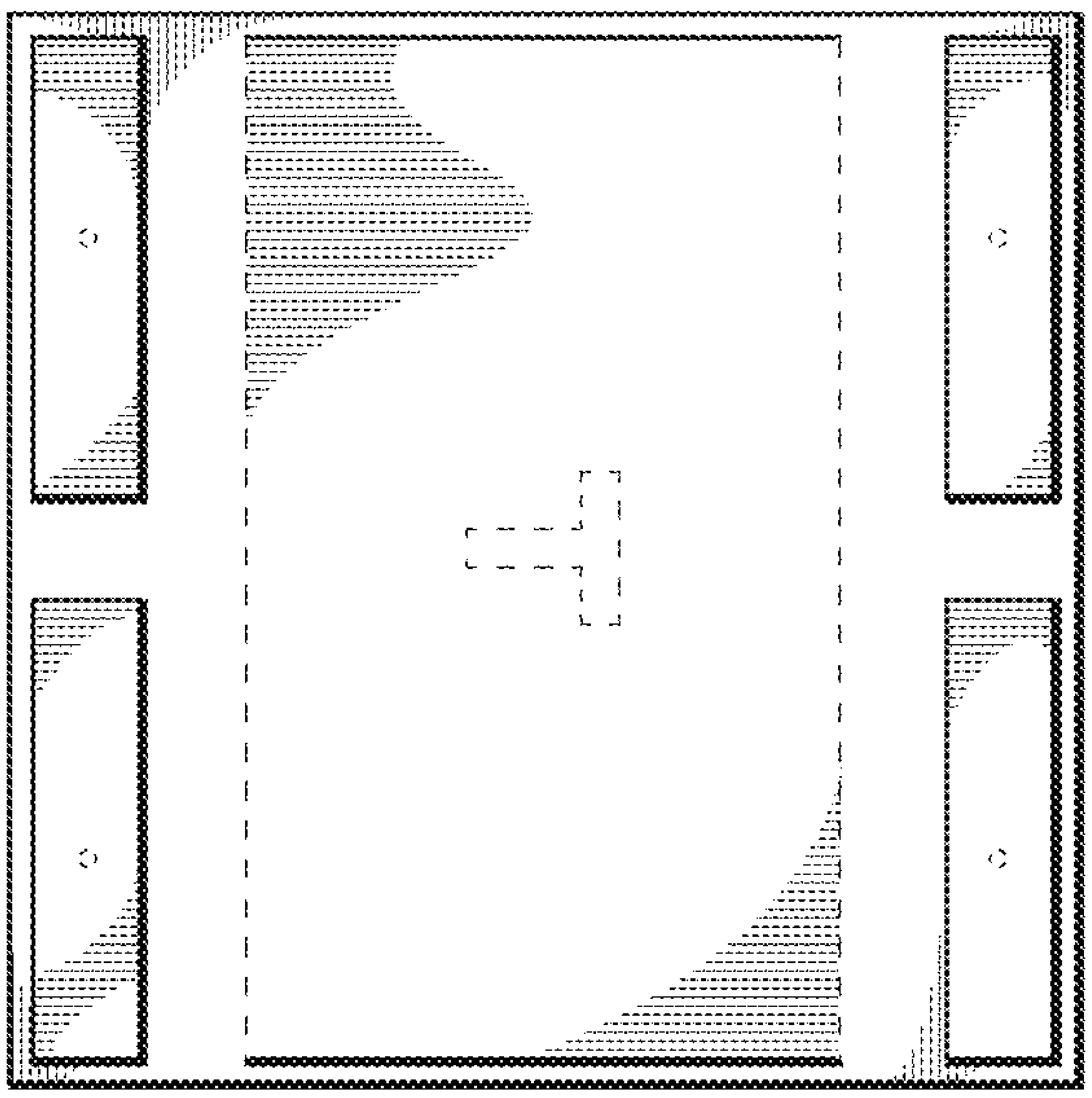


FIG. 10



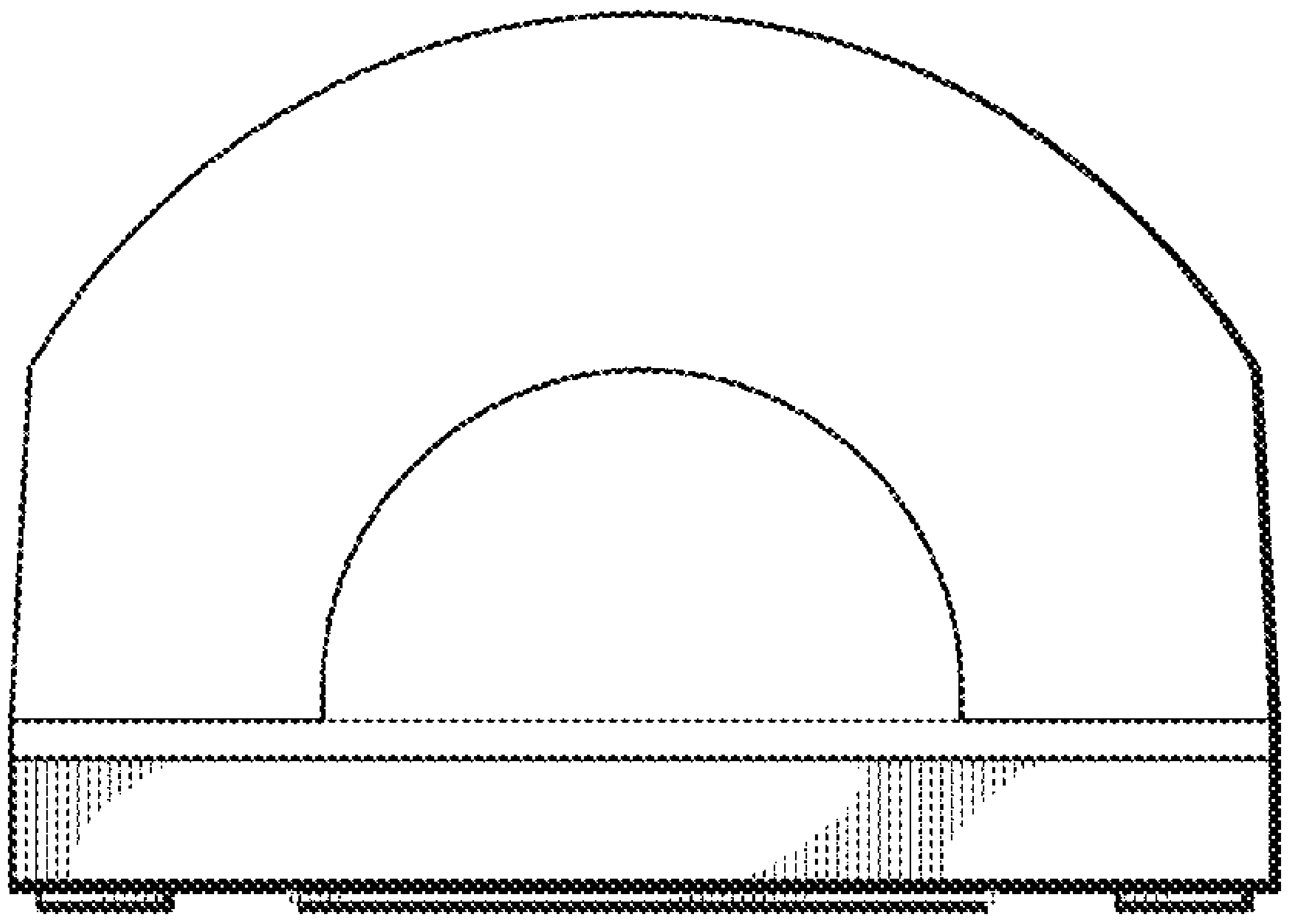


FIG. 11

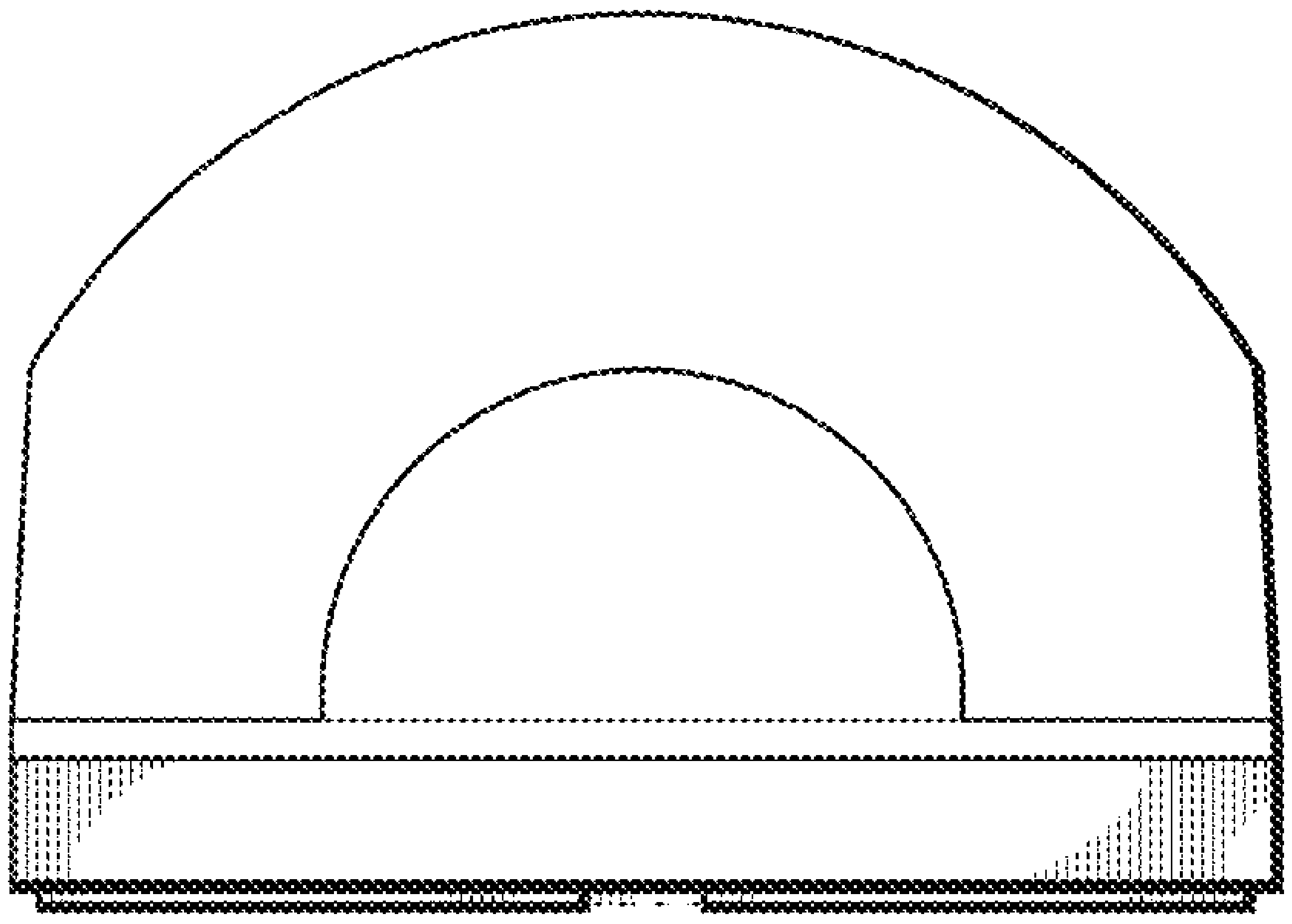


FIG. 12

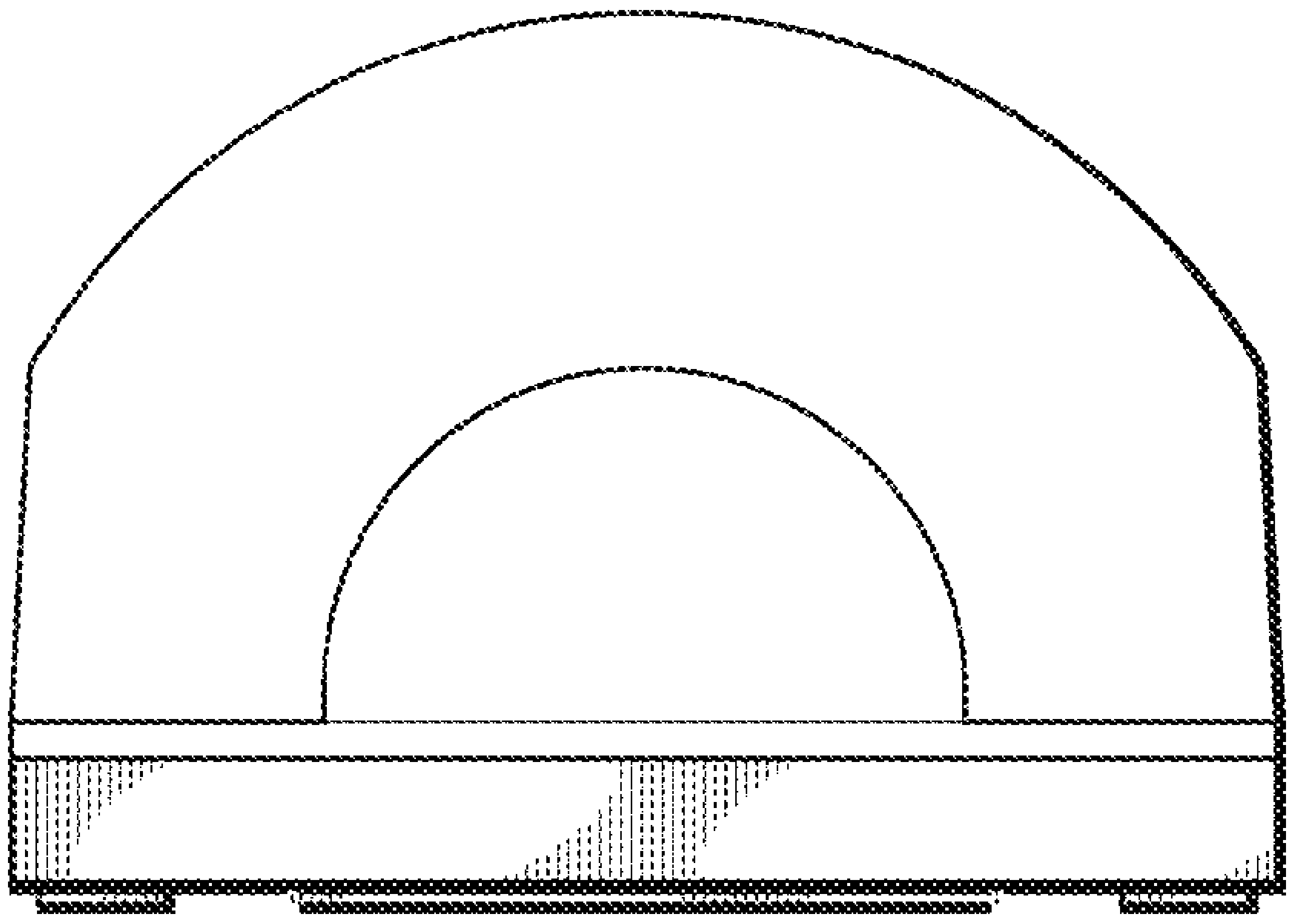


FIG. 13

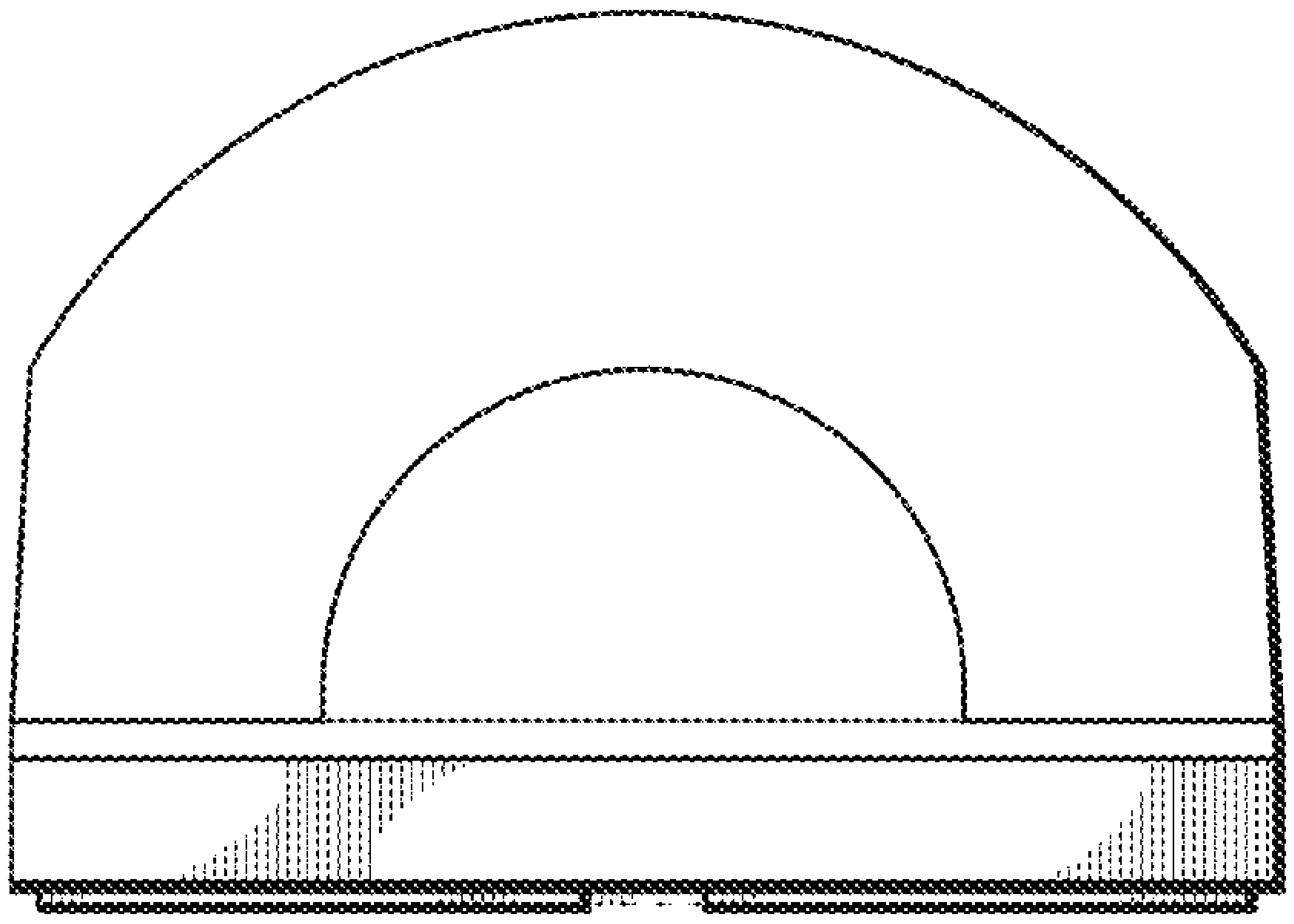


FIG. 14

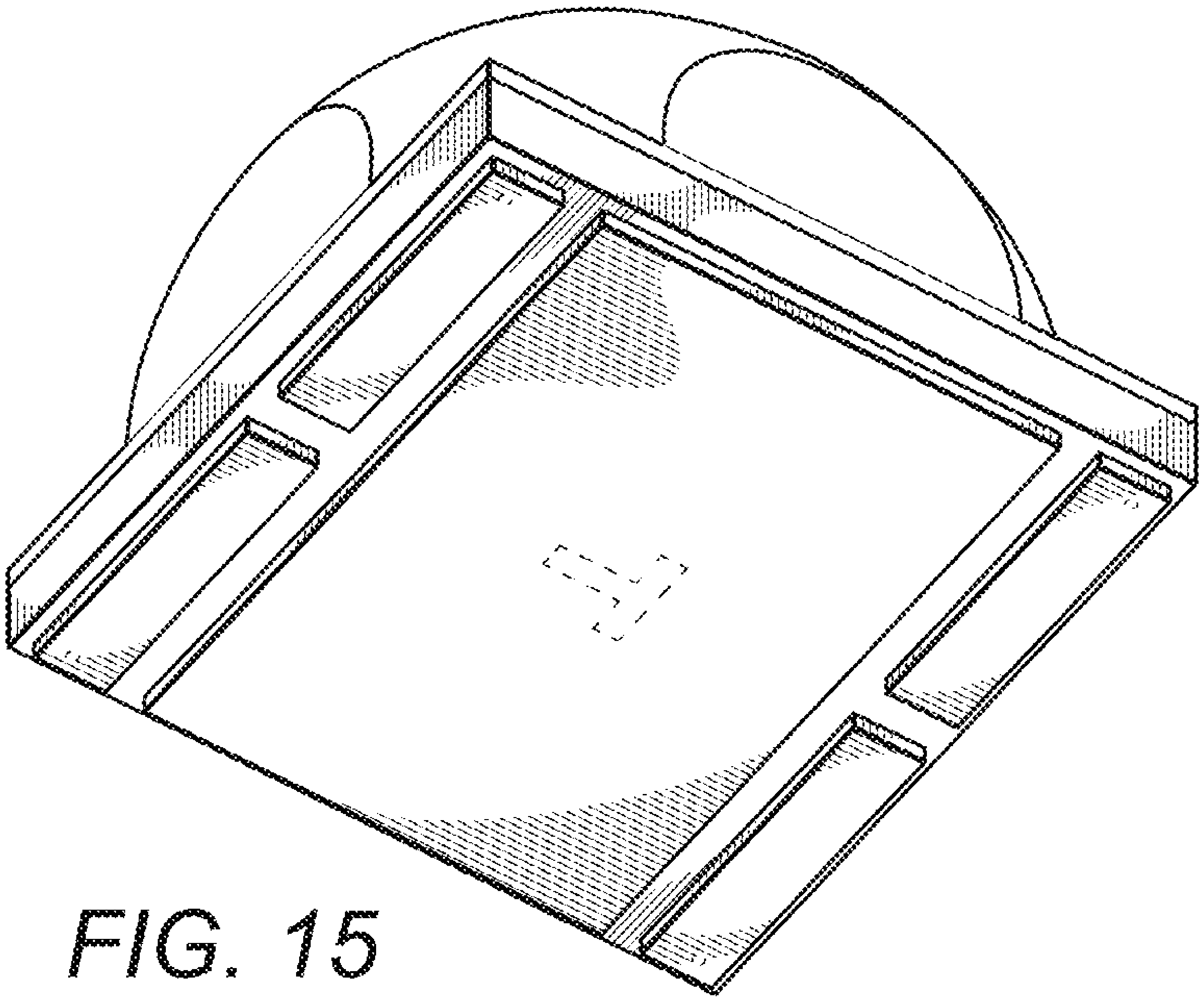


FIG. 15

FIG. 16

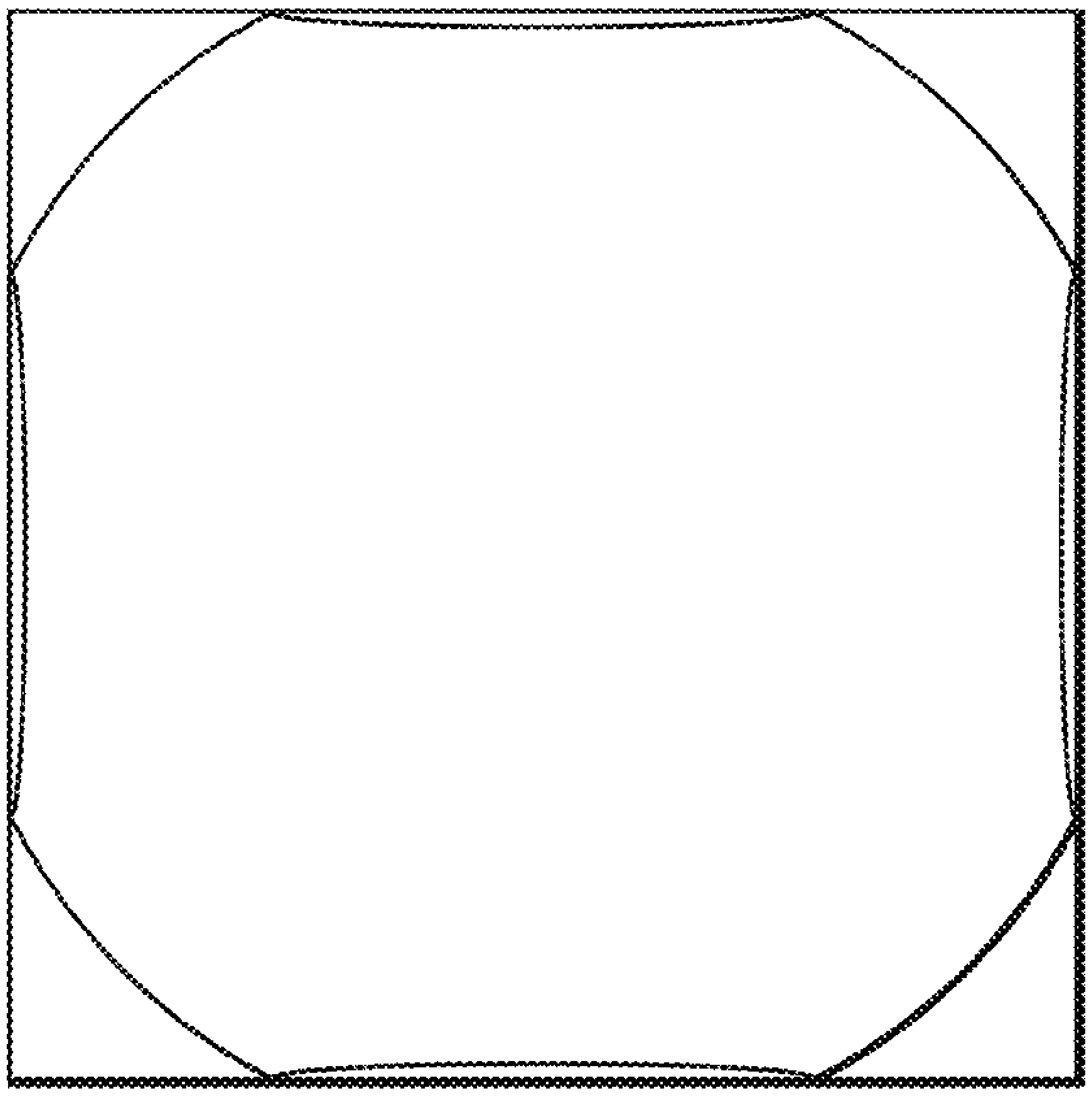
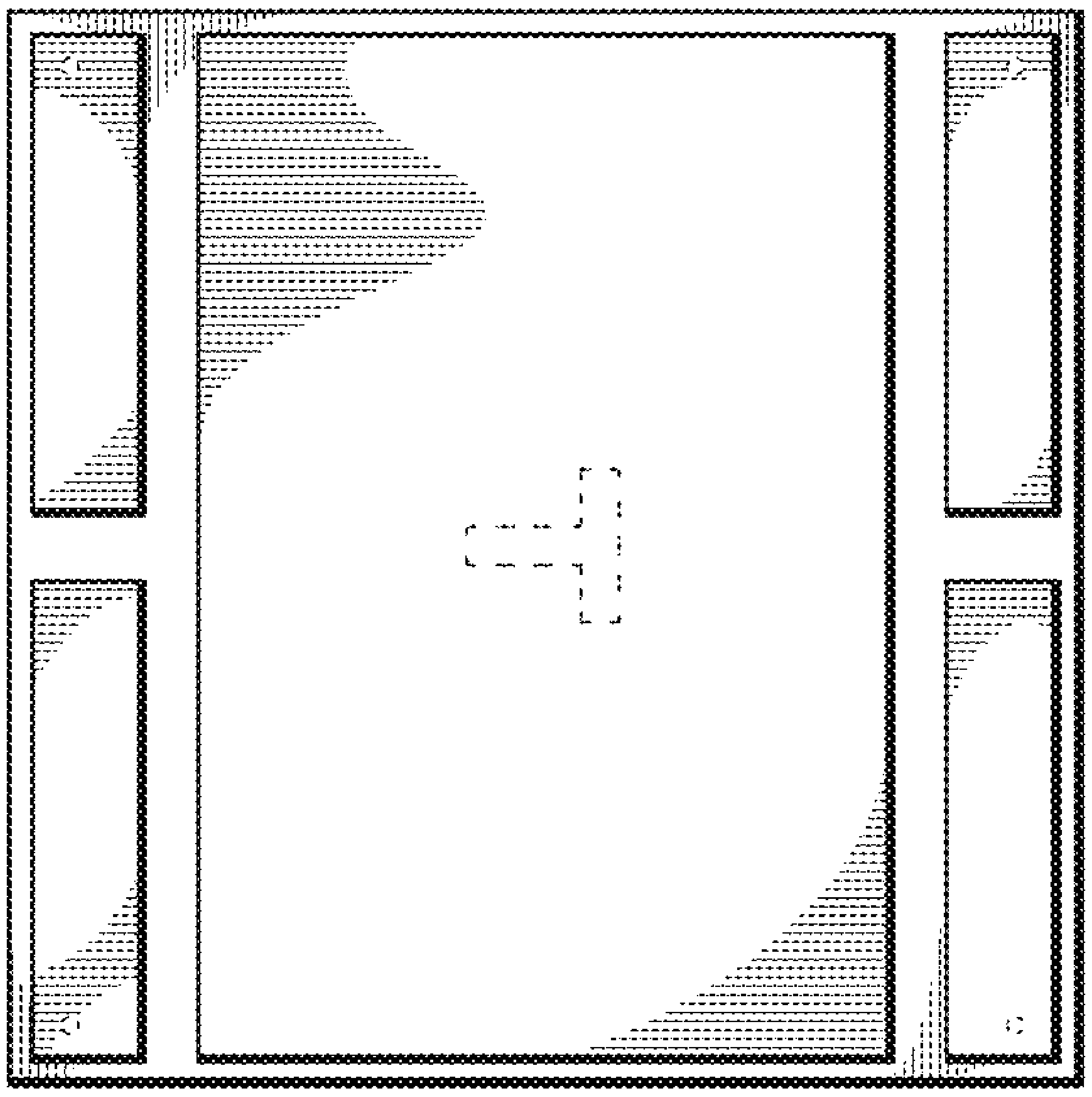


FIG. 17



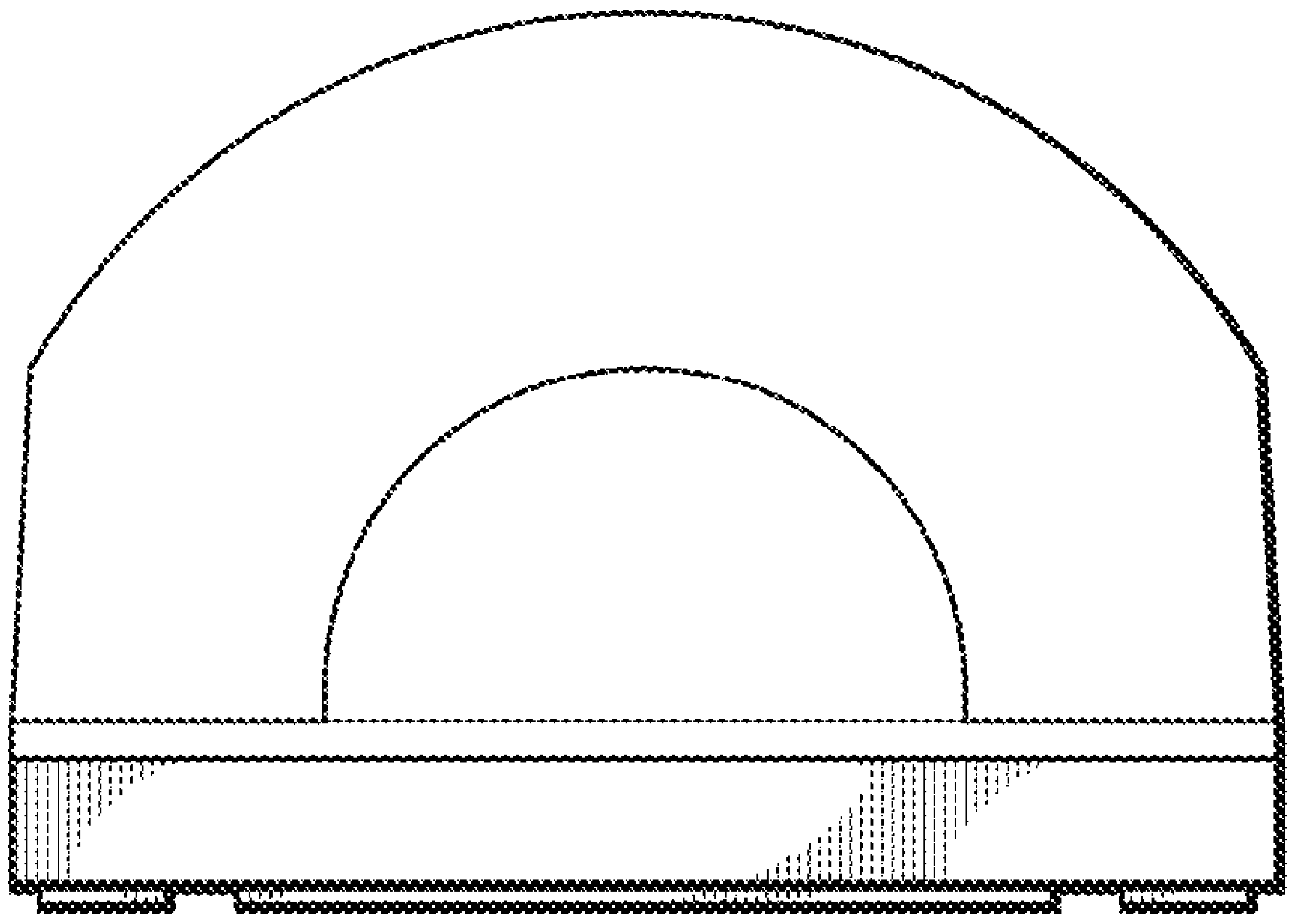


FIG. 18

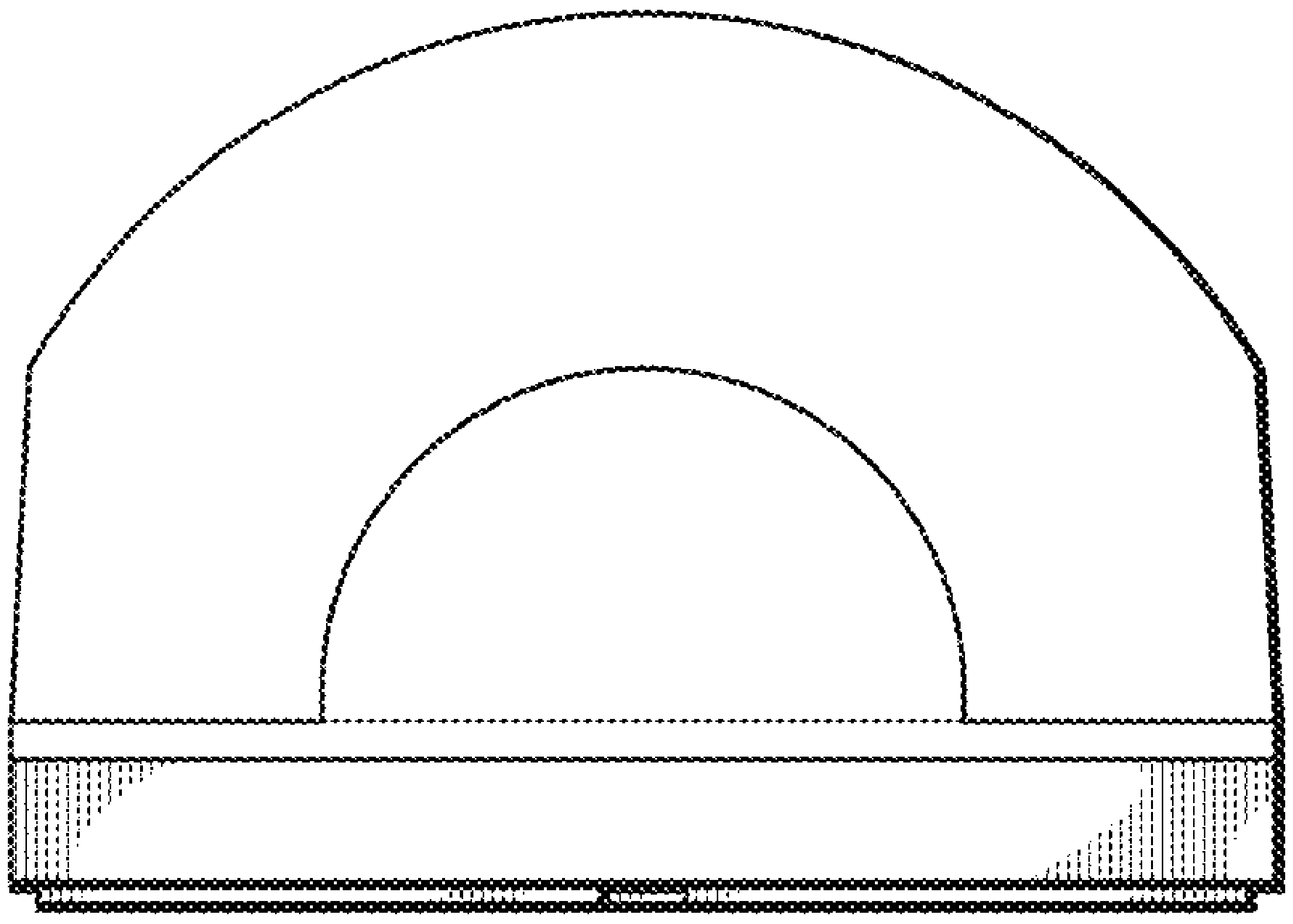


FIG. 19

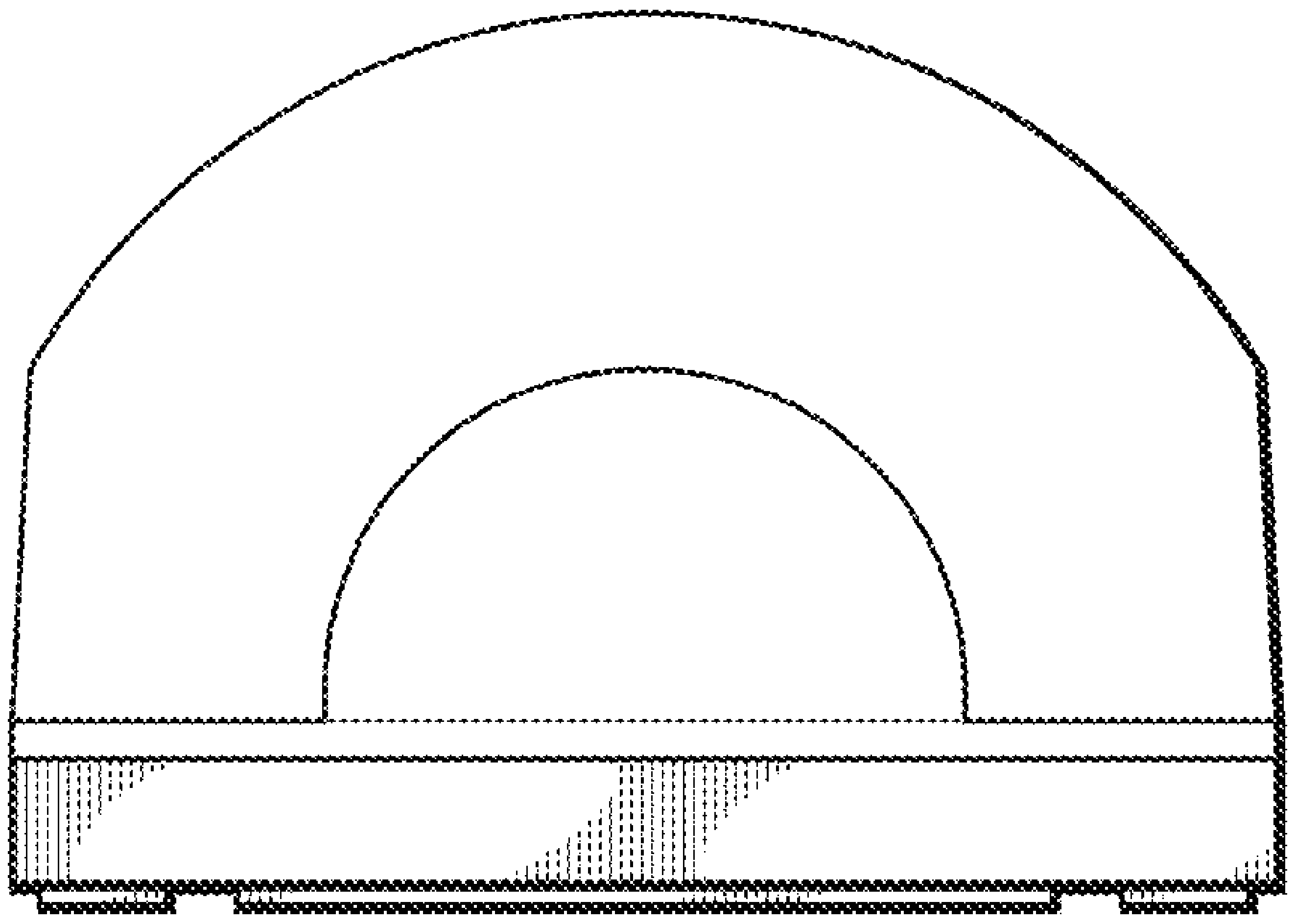


FIG. 20

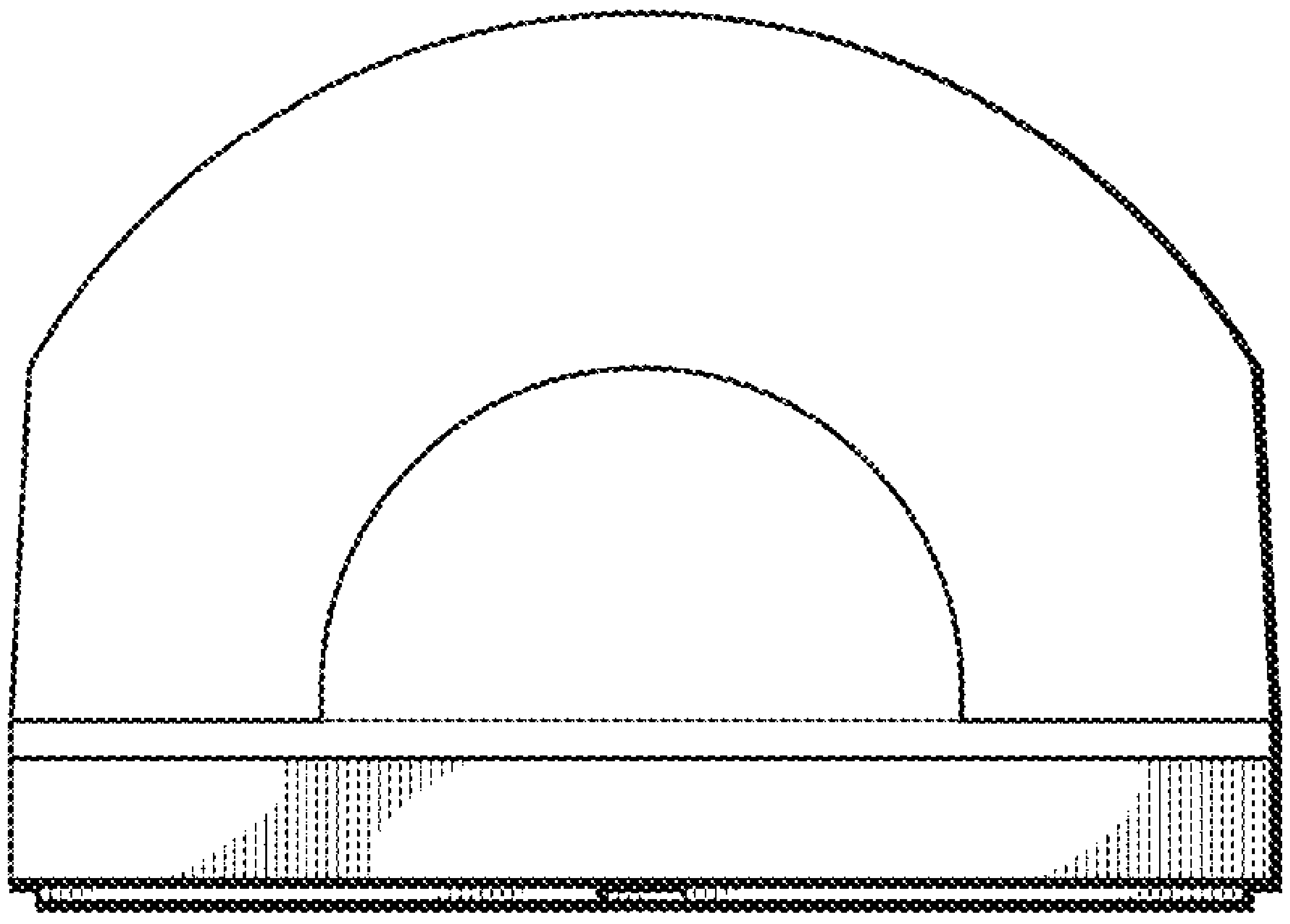


FIG. 21

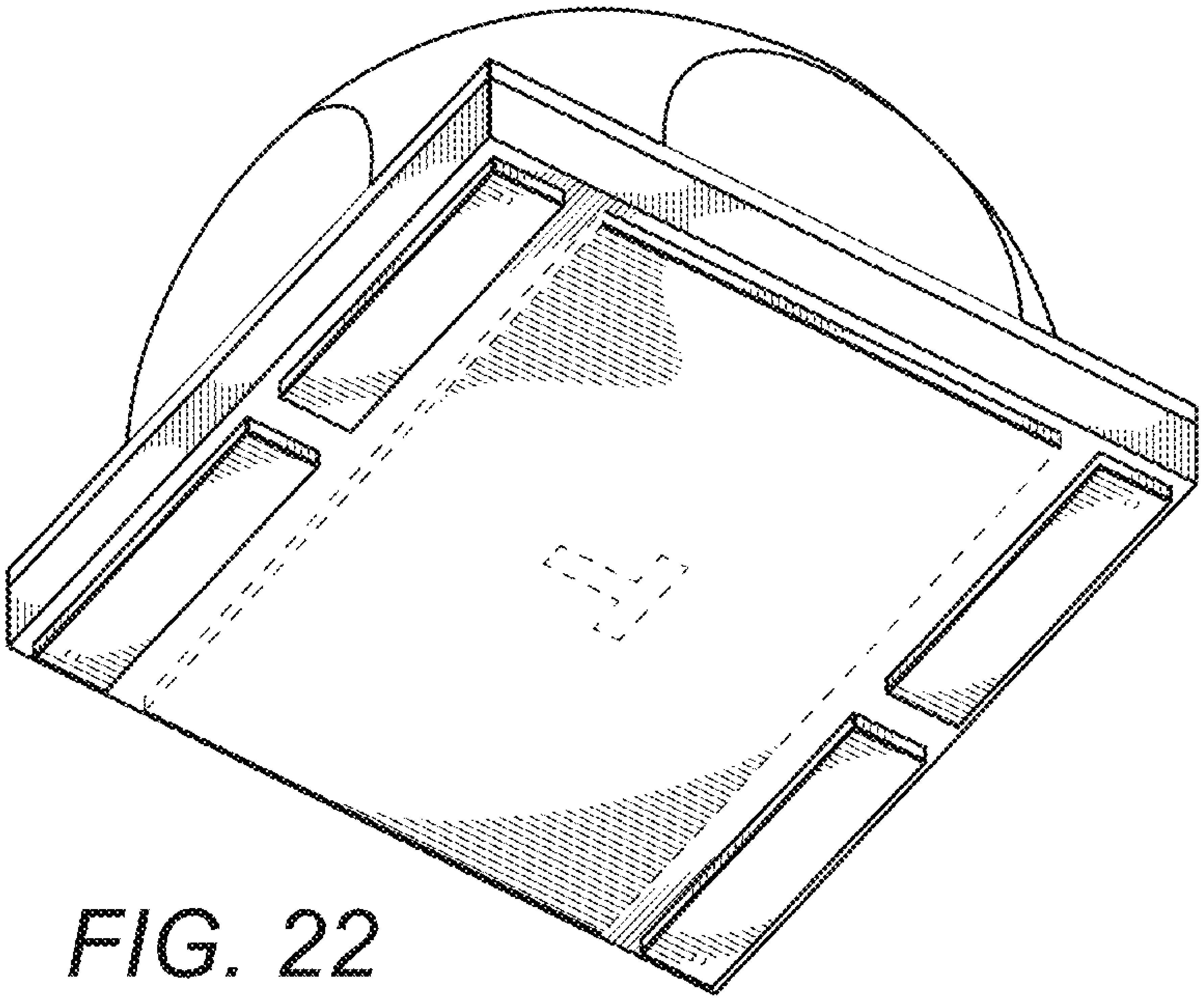


FIG. 22

FIG. 23

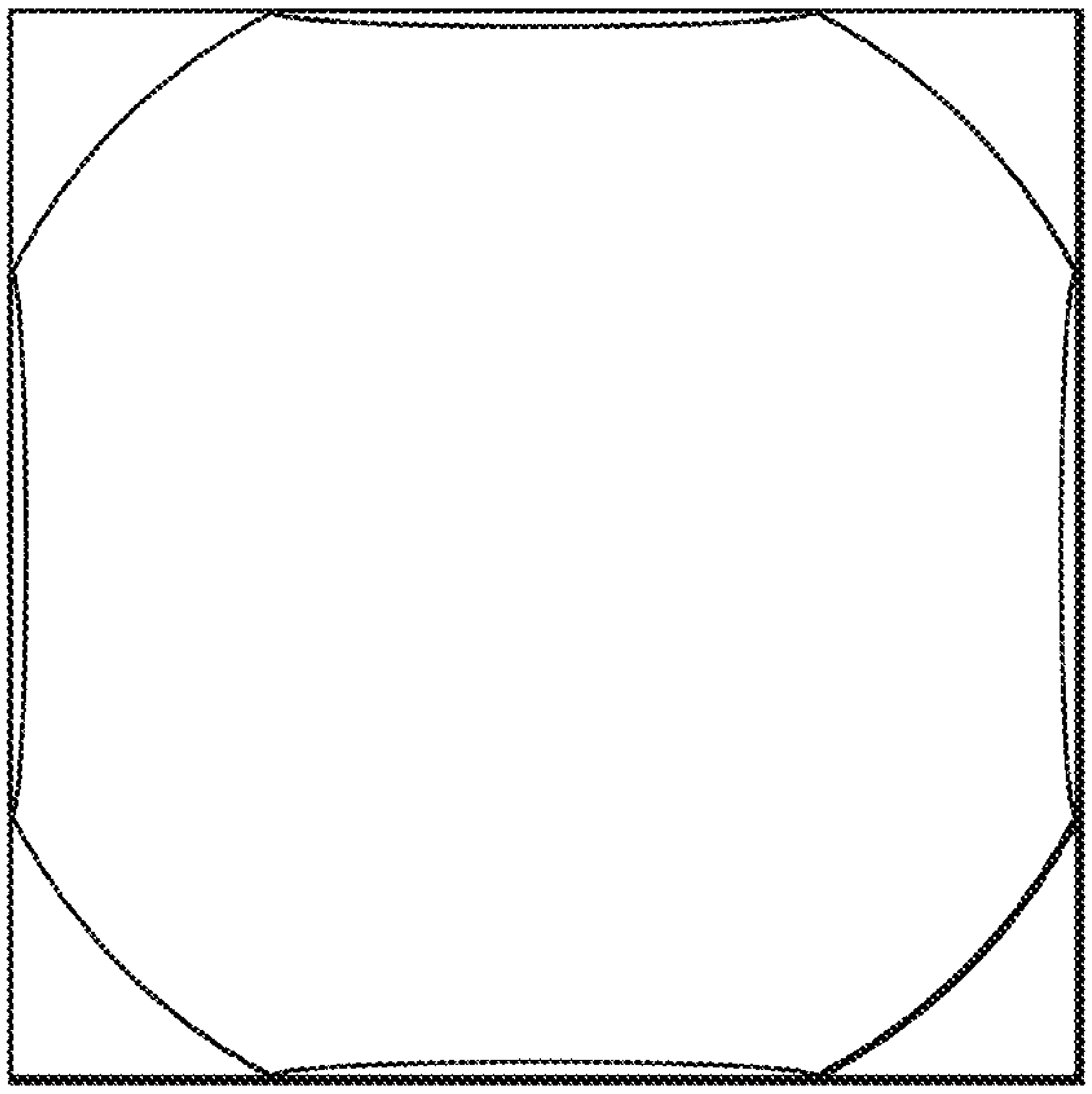
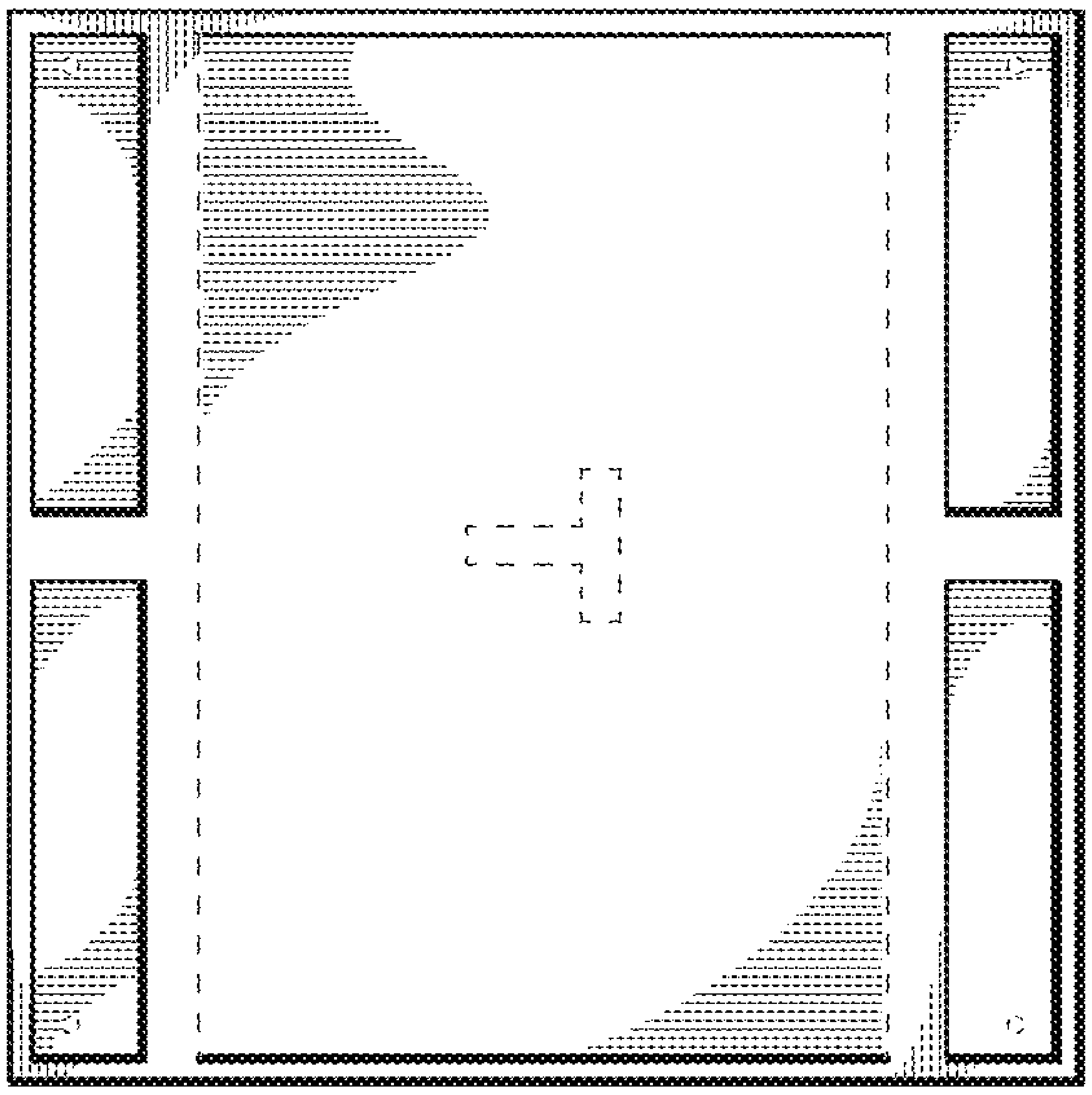


FIG. 24



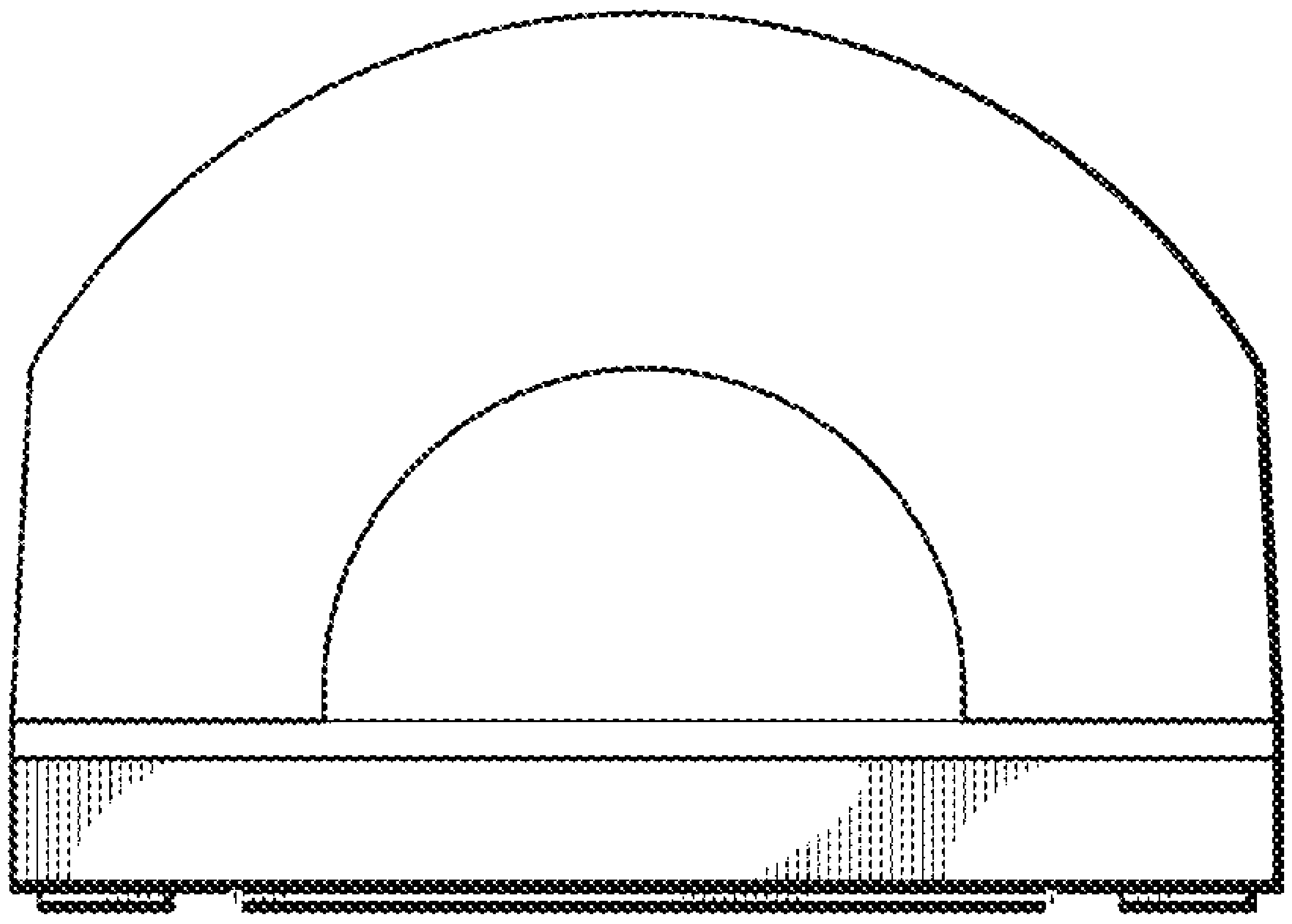


FIG. 25

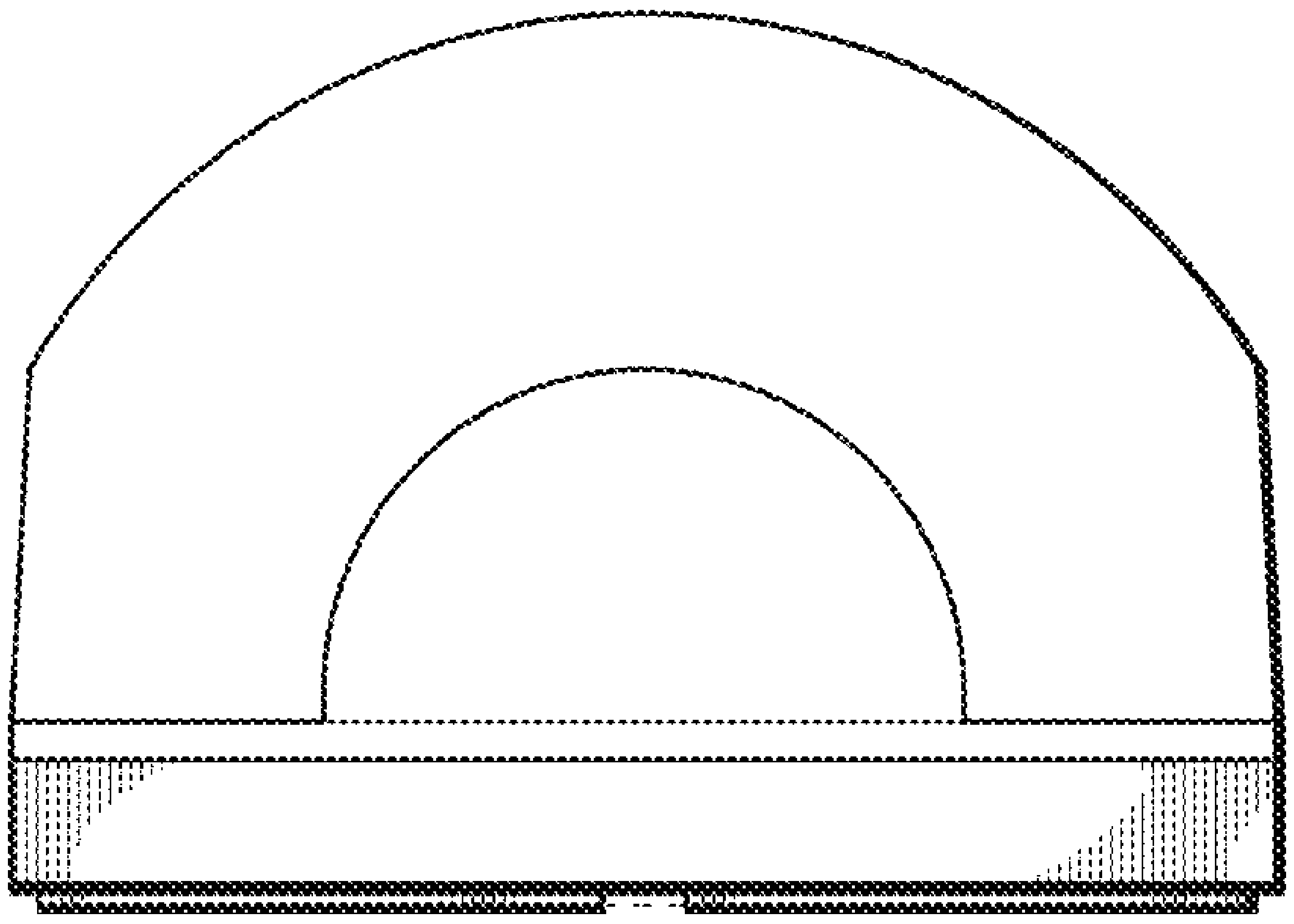


FIG. 26

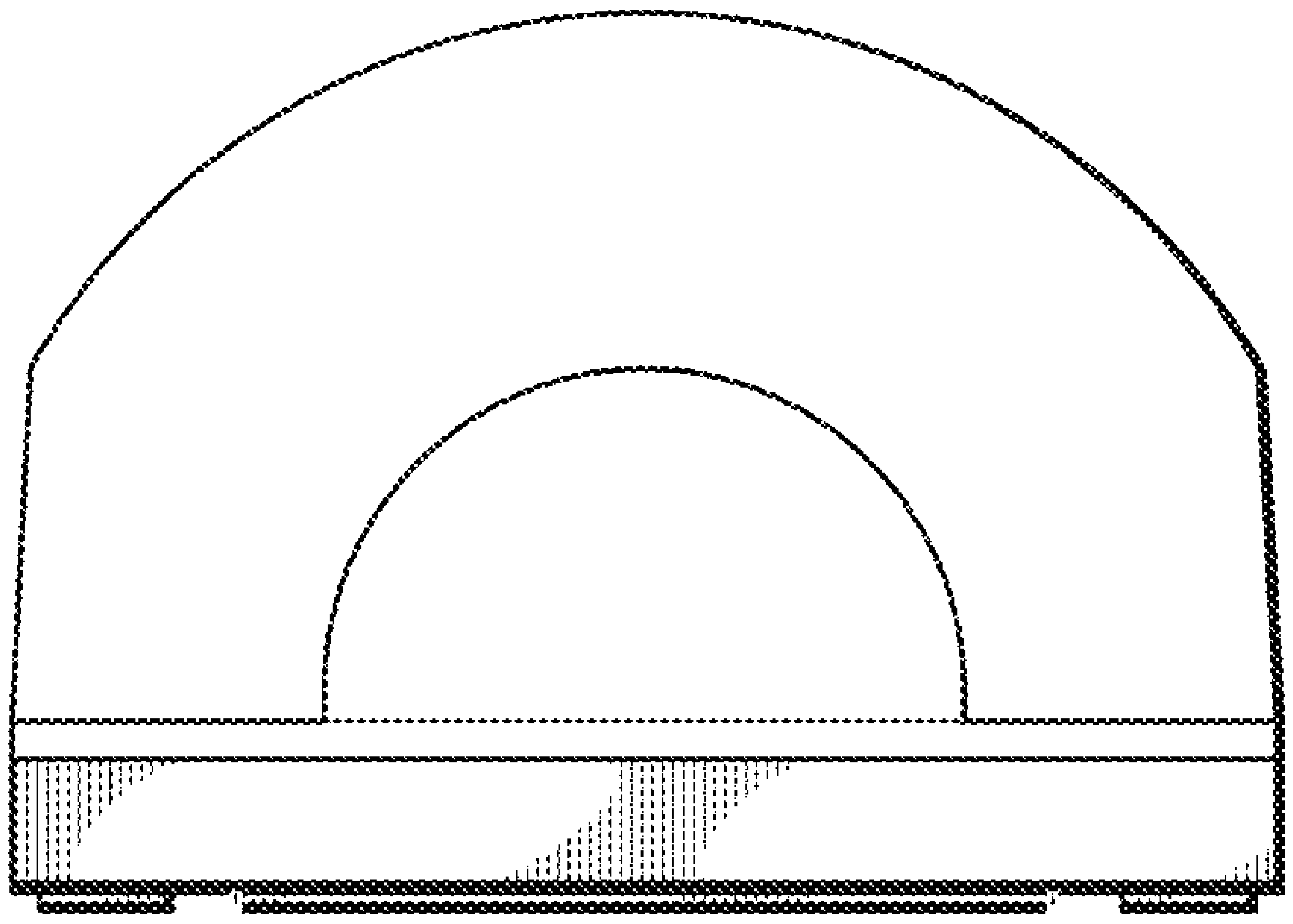


FIG. 27

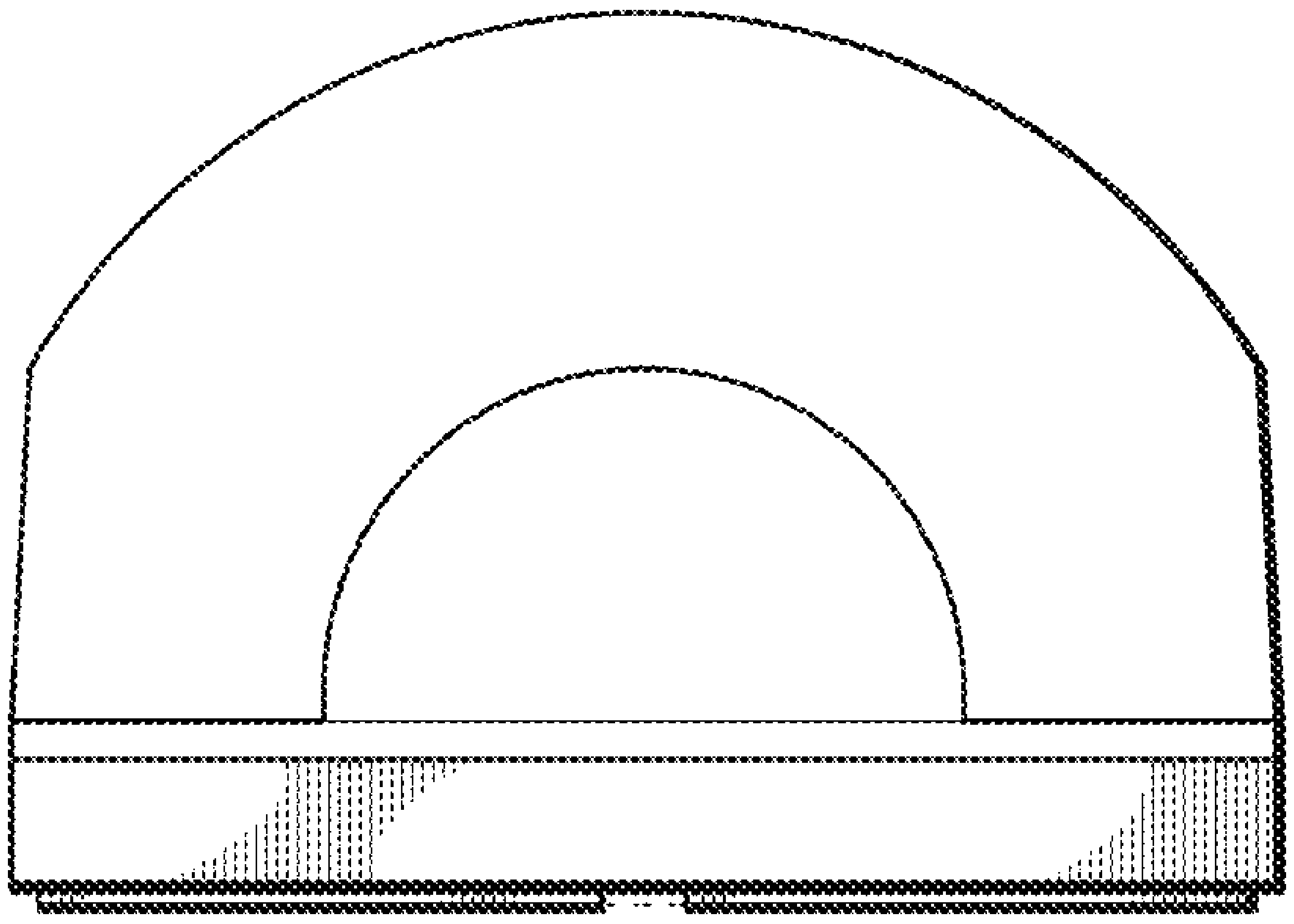


FIG. 28

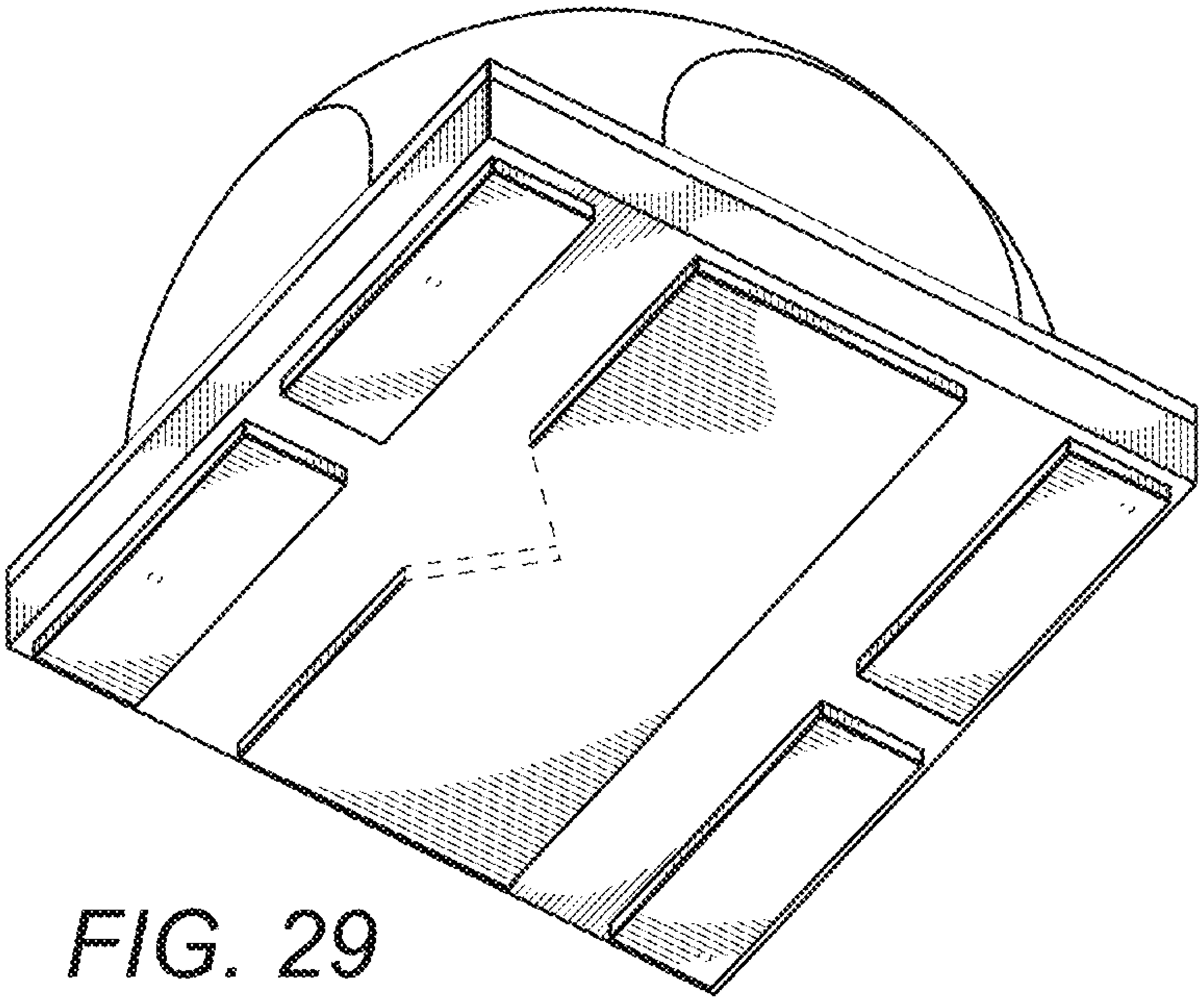


FIG. 29

FIG. 30

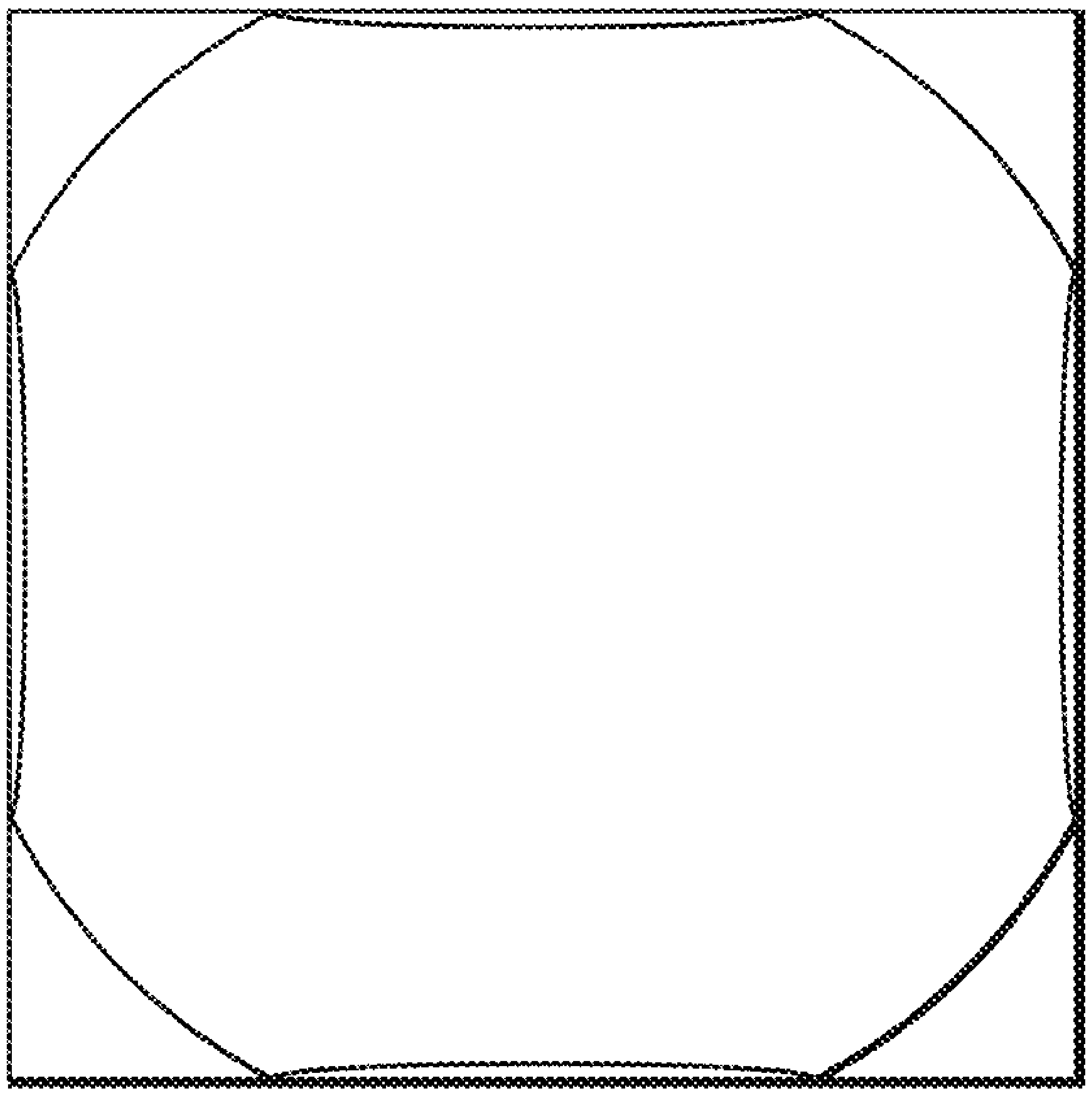
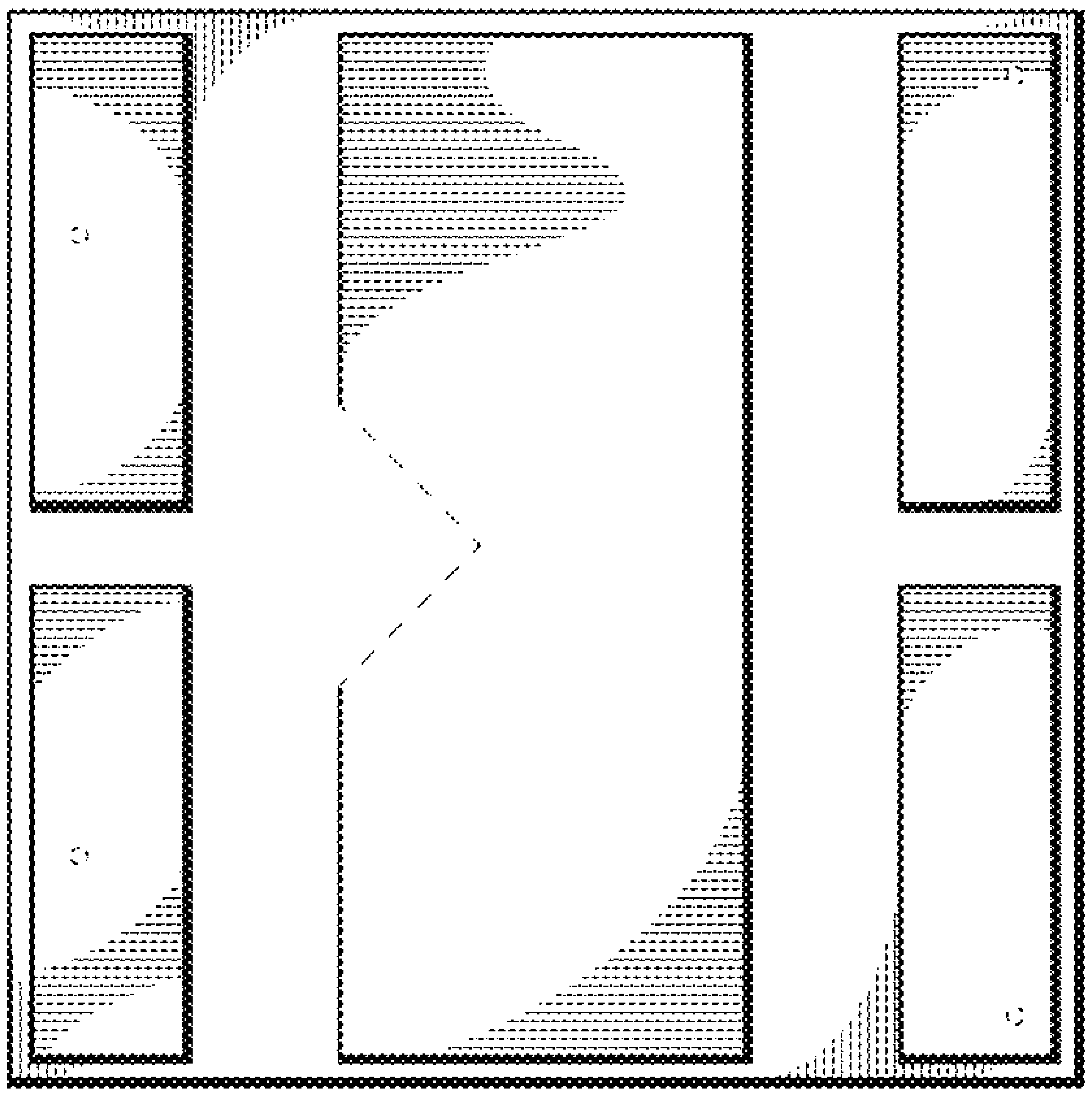


FIG. 31



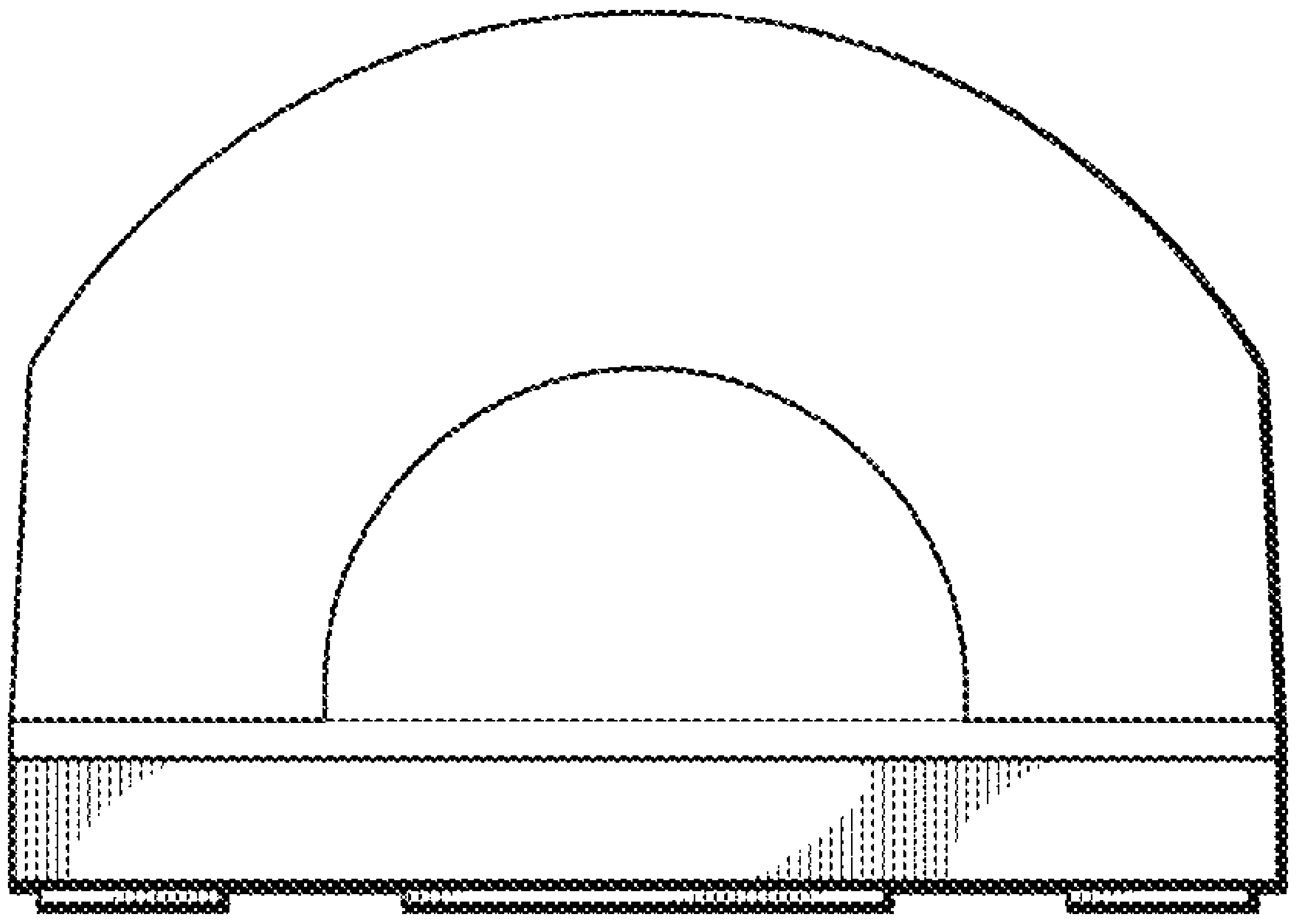


FIG. 32

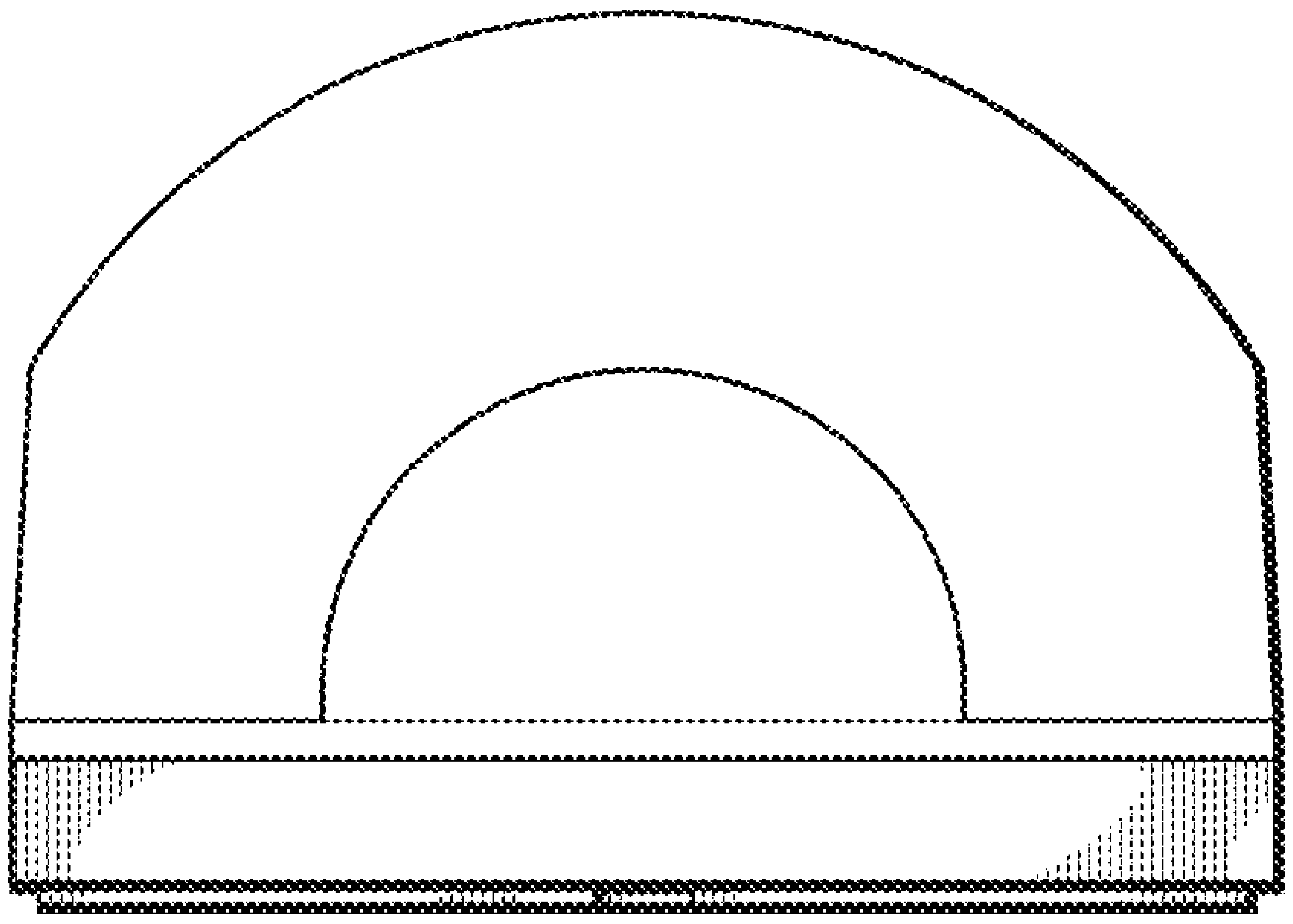


FIG. 33

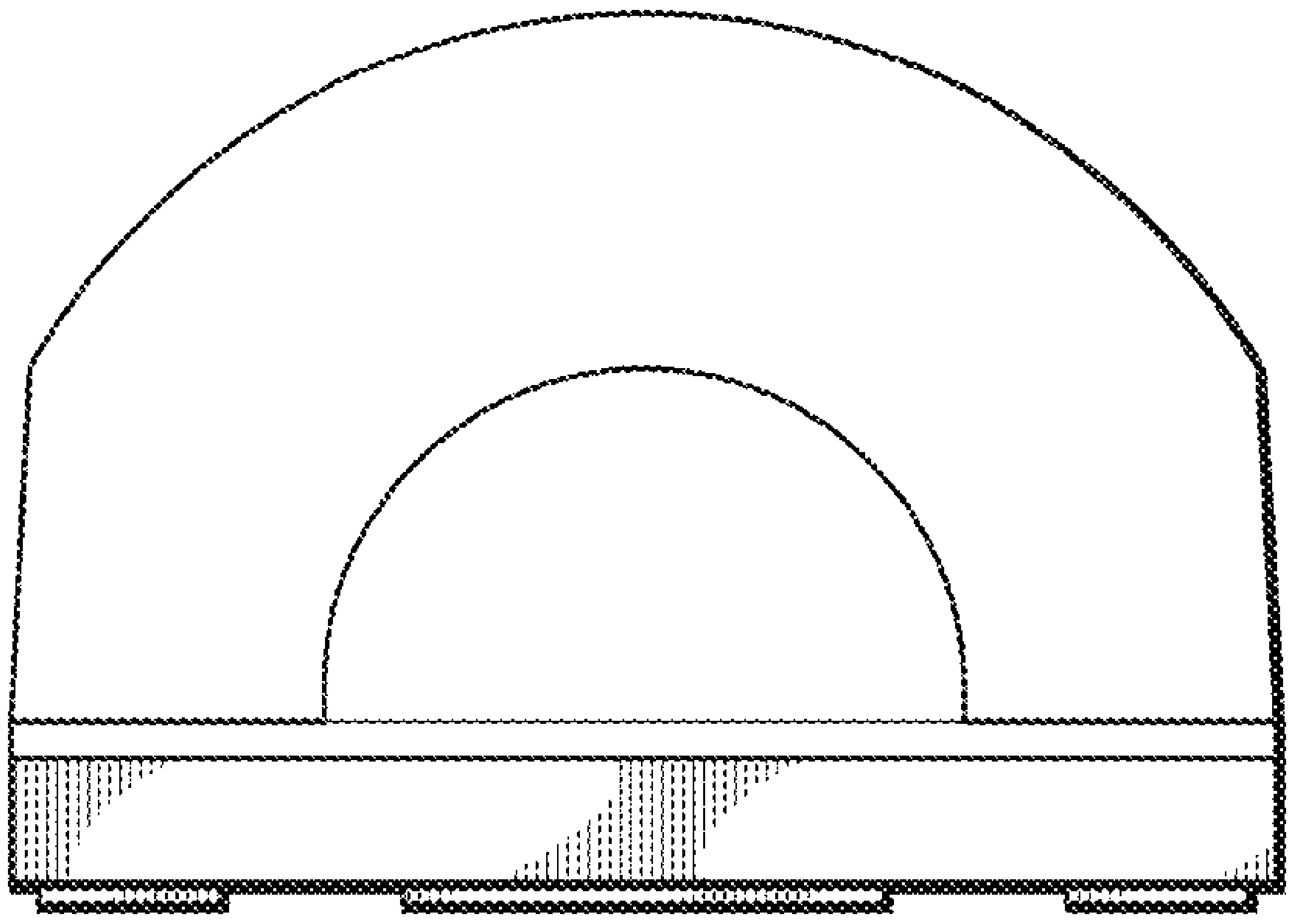


FIG. 34

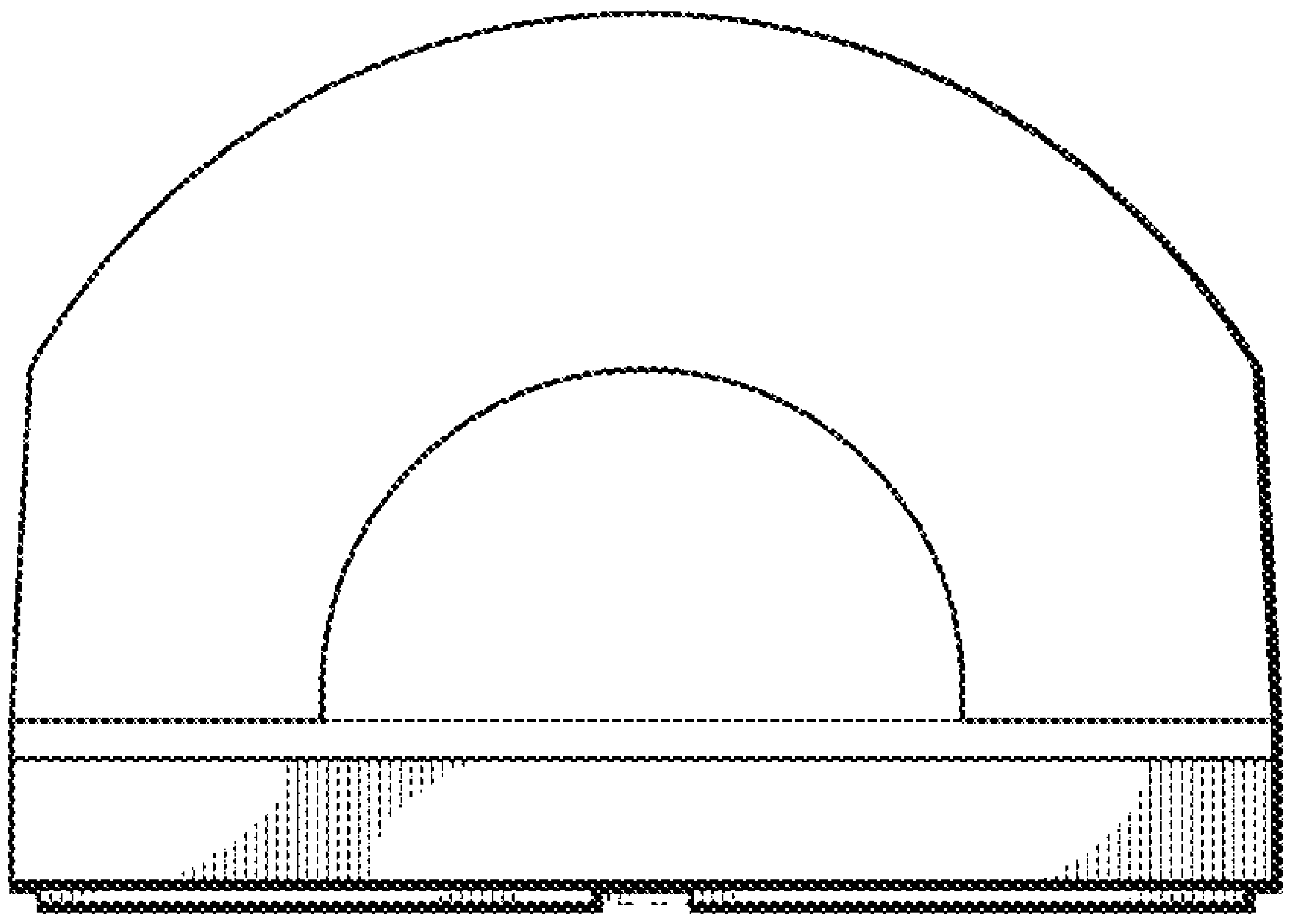


FIG. 35

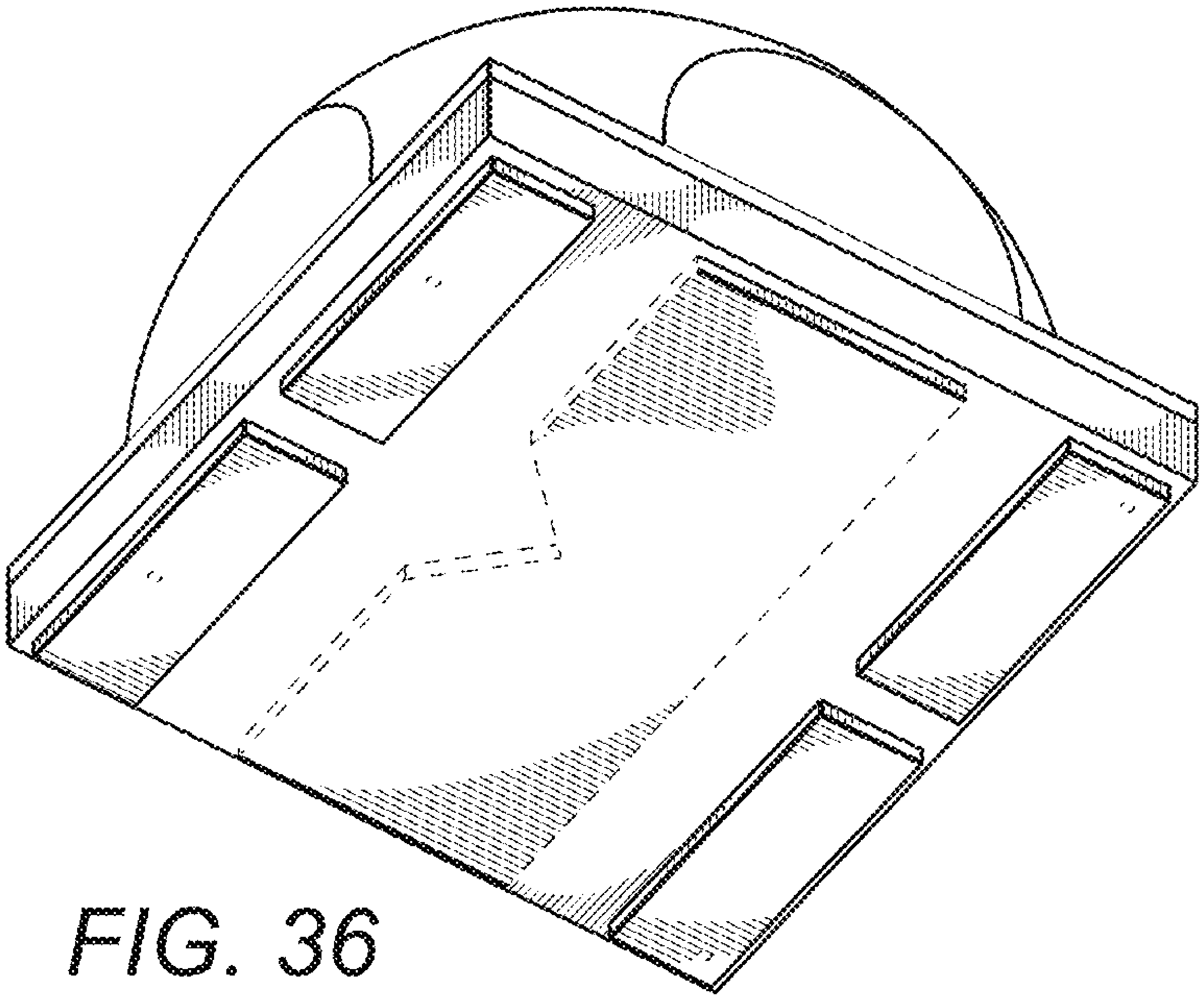


FIG. 36

FIG. 37

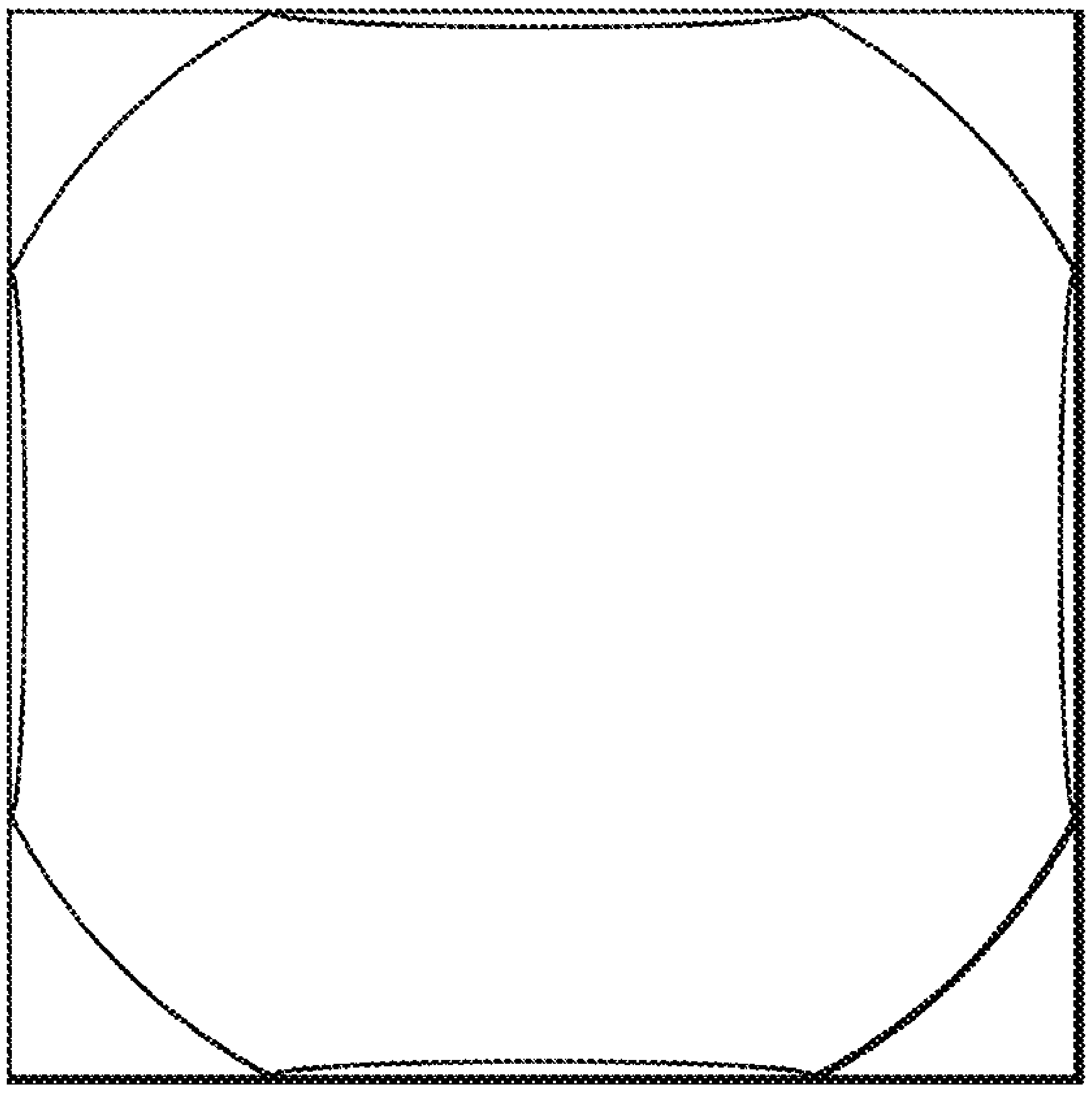
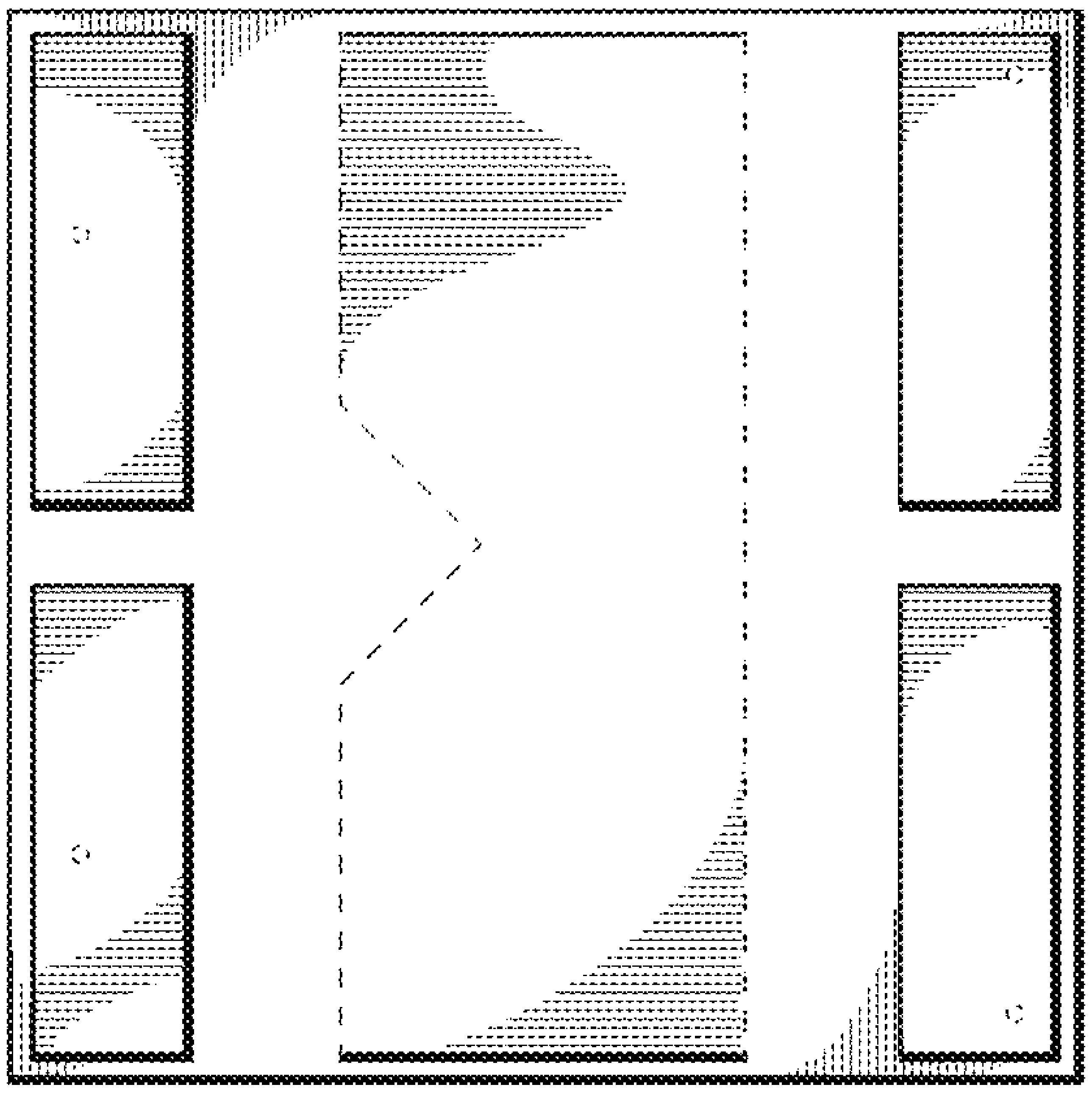


FIG. 38



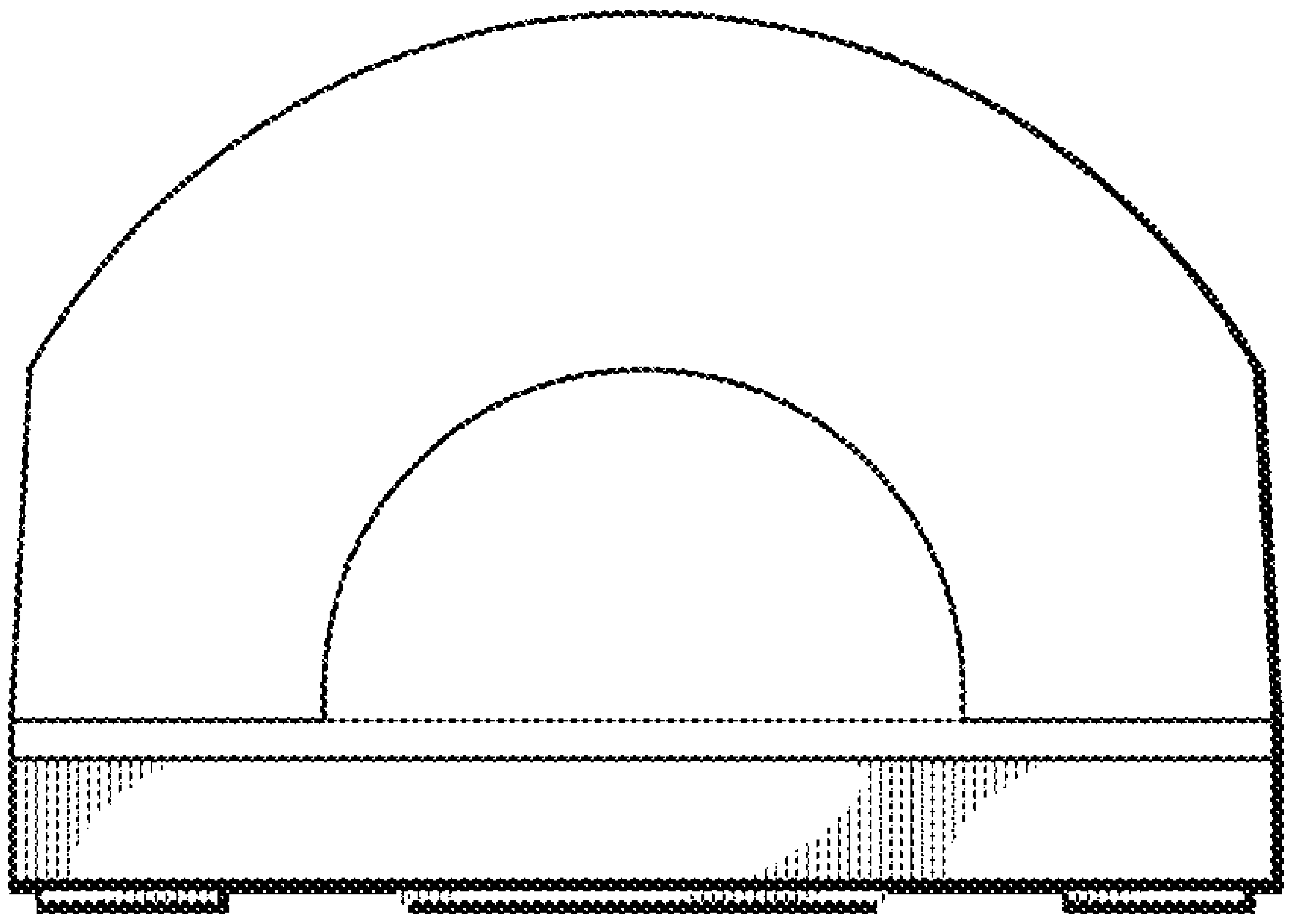


FIG. 39

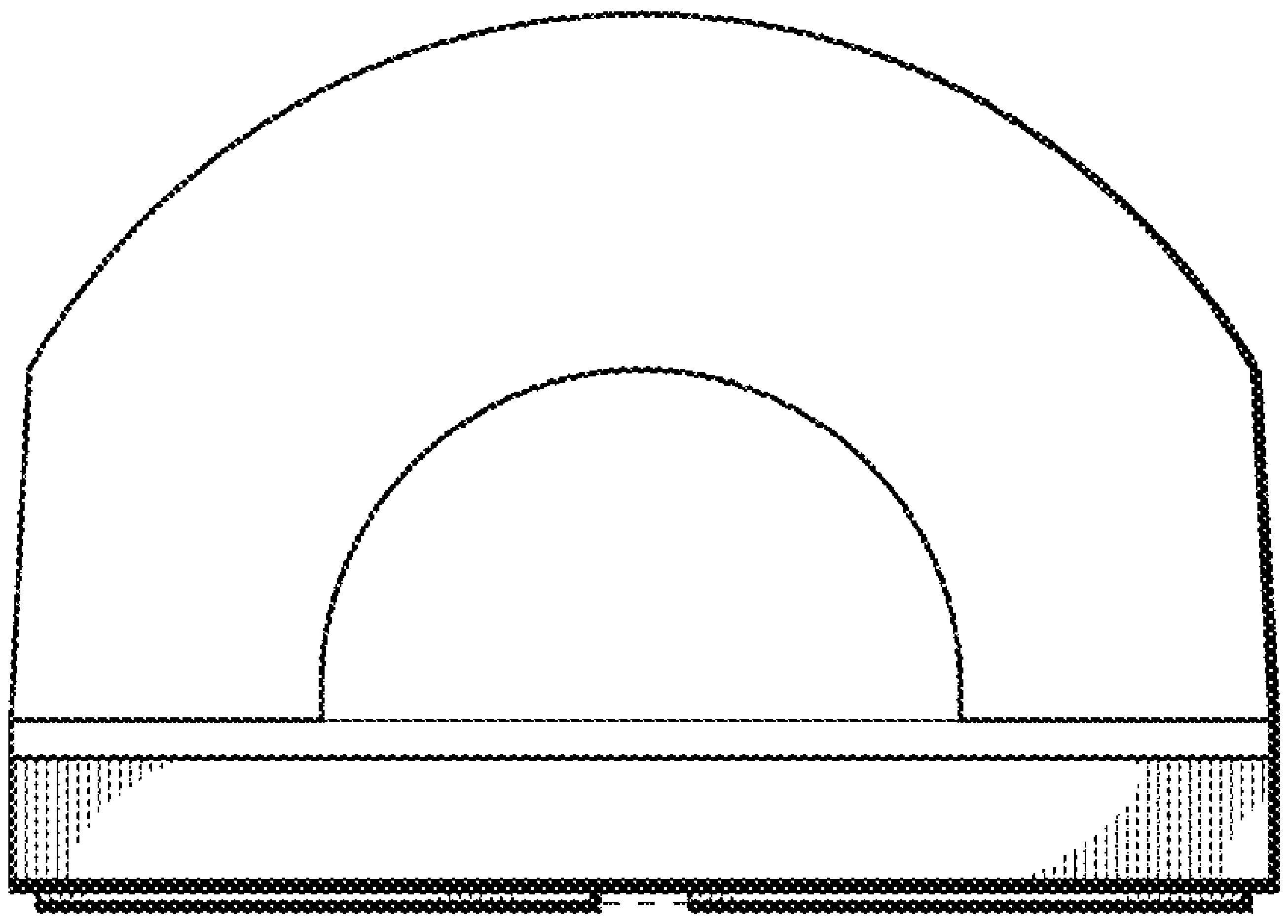


FIG. 40

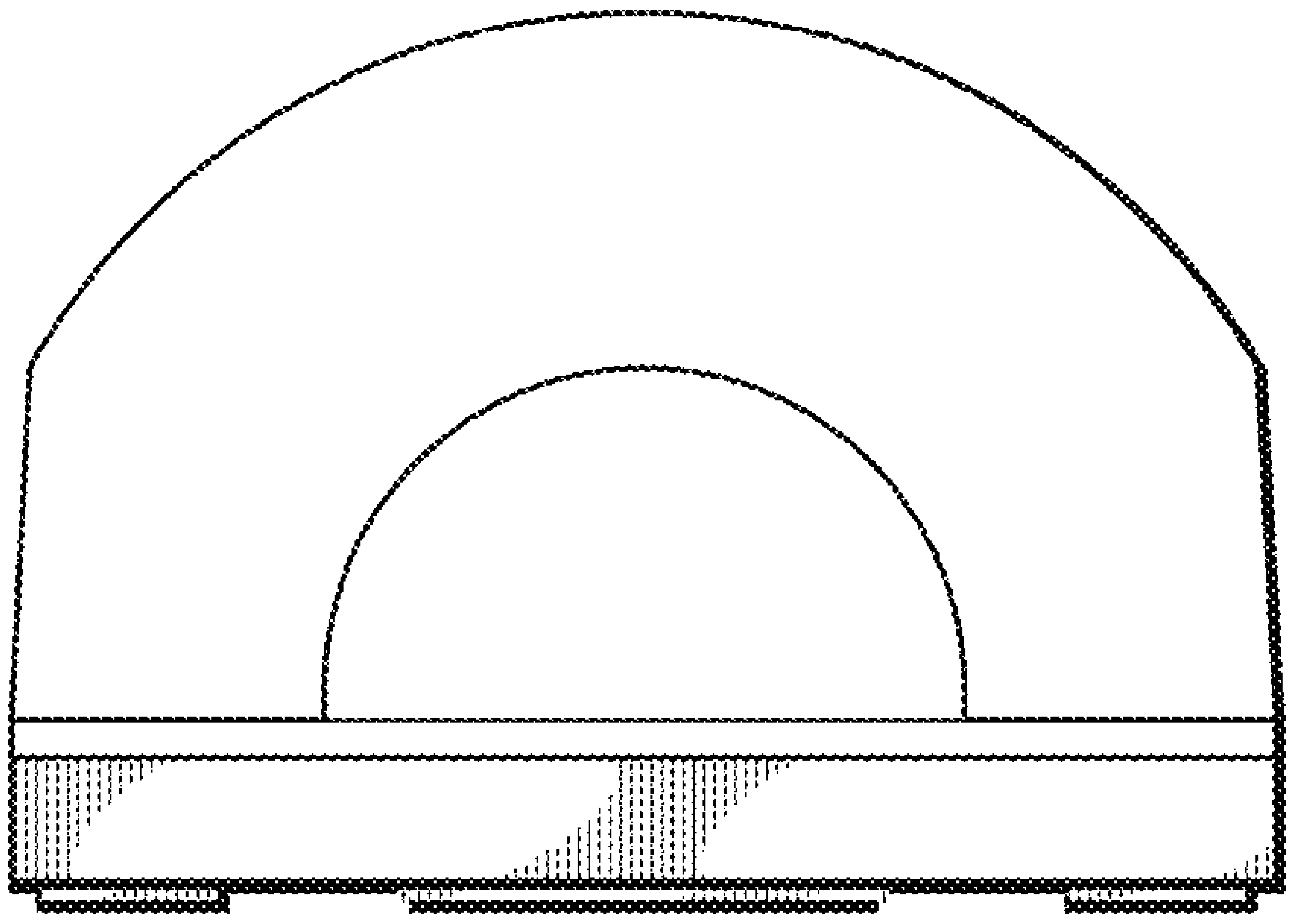


FIG. 41

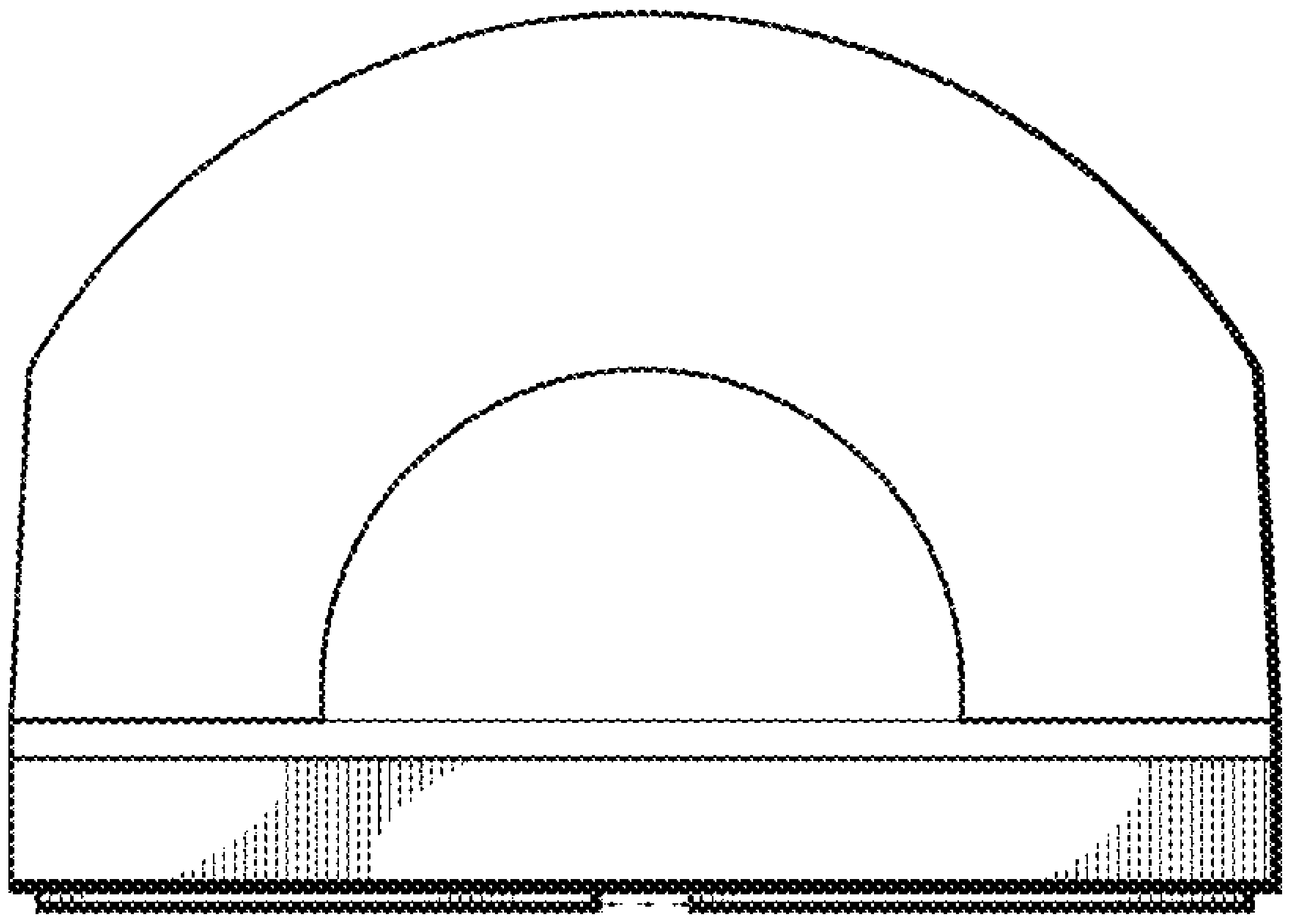


FIG. 42